PCF2129

Accurate RTC with integrated quartz crystal for industrial applications

Rev. 7 — 19 December 2014 **Product data sheet**

1. General description

The PCF2129 is a CMOS[1] Real Time Clock (RTC) and calendar with an integrated Temperature Compensated Crystal (Xtal) Oscillator (TCXO) and a 32.768 kHz quartz crystal optimized for very high accuracy and very low power consumption. The PCF2129 has a selectable I^{2}C-bus or SPI-bus, a backup battery switch-over circuit, a programmable watchdog function, a timestamp function, and many other features.

For a selection of NXP Real-Time Clocks, see Table 83 on page 75

2. Features and benefits

- Operating temperature range from –40 °C to +85 °C
- Temperature Compensated Crystal Oscillator (TCXO) with integrated capacitors
- Typical accuracy:
    - PCF2129AT: ±3 ppm from –15 °C to +60 °C
    - PCF2129T: ±3 ppm from –30 °C to +80 °C
- Integration of a 32.768 kHz quartz crystal and oscillator in the same package
- Provides year, month, day, weekday, hours, minutes, seconds, and leap year correction
- Timestamp function
    - with interrupt capability
    - detection of two different events on one multilevel input pin (for example, for tamper detection)
- Two line bidirectional 400 kHz Fast-mode I^{2}C-bus interface
- 3 line SPI-bus with separate data input and output (maximum speed 6.5 Mbit/s)
- Battery backup input pin and switch-over circuitry
- Battery backed output voltage
- Battery low detection function
- Power-On Reset Override (PORO)
- Oscillator stop detection function
- Interrupt output (open-drain)
- Programmable 1 second or 1 minute interrupt
- Programmable watchdog timer with interrupt
- Programmable alarm function with interrupt capability
- Programmable square output

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[1] The definition of the abbreviations and acronyms used in this data sheet can be found in Section 20.

- Clock operating voltage: 1.8 V to 4.2 V
- Low supply current: typical 0.70 μA at V_{DD} = 3.3 V

3. Applications

- Electronic metering for electricity, water, and gas
- Precision timekeeping
- Access to accurate time of the day
- GPS equipment to reduce time to first fix
- Applications that require an accurate process timing
- Products with long automated unattended operation time

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
PCF2129AT	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
PCF2129T	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1

4.1 Ordering options

Table 2. Ordering options

Product type number	Orderable part number	Sales item (12NC)	Delivery form	IC revision
PCF2129AT/2	PCF2129AT/2,518	935295732518	tape and reel, 13 inch, dry pack	2
PCF2129T/2	PCF2129T/2,518	935297464518	tape and reel, 13 inch, dry pack	2

5. Marking

Table 3. Marking codes

Product type number	Marking code
PCF2129AT/2	PCF2129AT
PCF2129T/2	PCF2129T

6. Block diagram

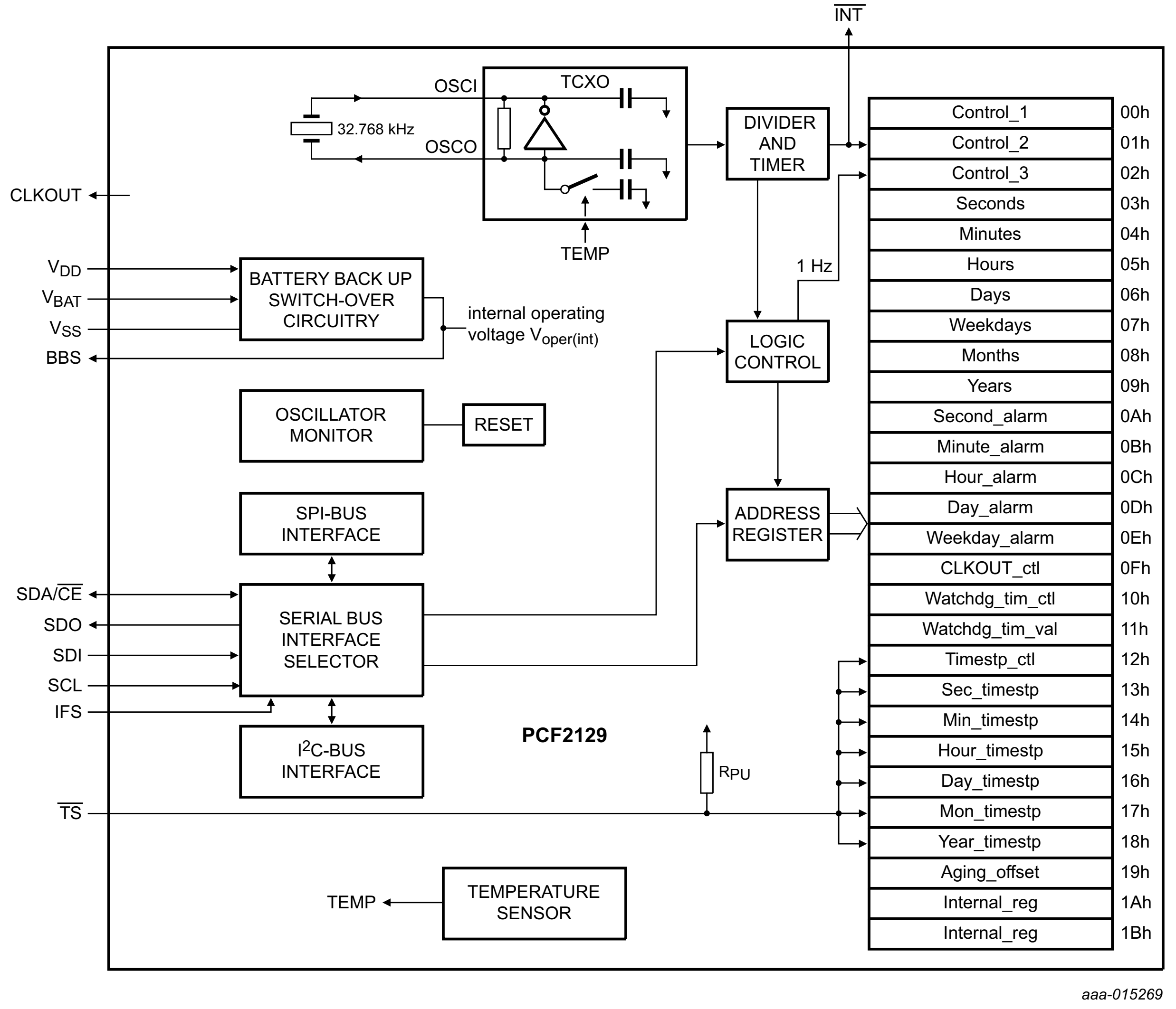
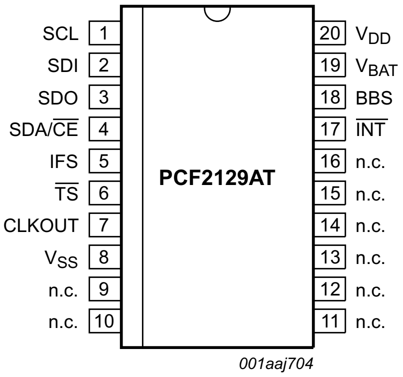


Fig 1. Block diagram of PCF2129

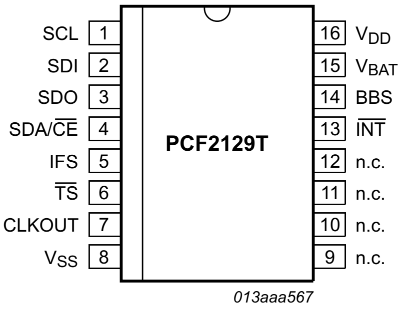
7. Pinning information

7.1 Pinning



Top view. For mechanical details, see Figure 50.

Fig 2. Pin configuration for PCF2129AT (SO20)



Top view. For mechanical details, see Figure 50.

Fig 3. Pin configuration for PCF2129T (SO16)

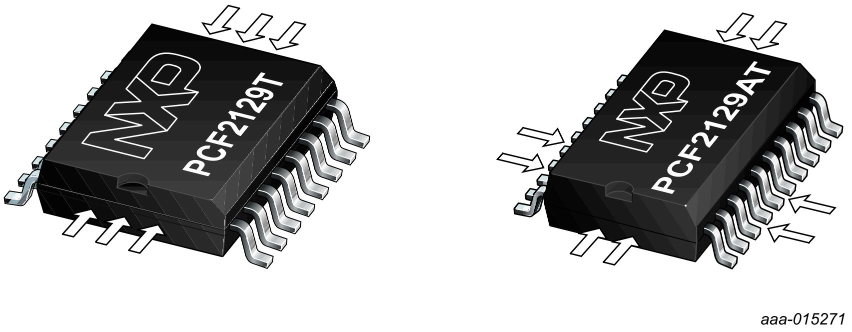


Fig 4. Position of the stubs from the package assembly process

After lead forming and cutting, there remain stubs from the package assembly process. These stubs are present at the edge of the package as illustrated in Figure 4. The stubs are at an electrical potential. To avoid malfunction of the PCF2129, it has to be ensured that they are not shorted with another electrical potential (e.g. by condensation).

7.2 Pin description

Table 4. Pin description of PCF2129

Input or input/output pins must always be at a defined level (V_{SS} or V_{DD}) unless otherwise specified.

Symbol	Pin		Description
	PCF2129AT	PCF2129T	
SCL	1	1	combined serial clock input for both I^2C-bus and SPI-bus
SDI	2	2	serial data input for SPI-bus connect to pin V_{SS} if I^2C-bus is selected
SDO	3	3	serial data output for SPI-bus, push-pull
SDA/$\overline{\text{CE}}$	4	4	combined serial data input and output for the I^2C-bus and chip enable input (active LOW) for the SPI-bus
IFS	5	5	interface selector input connect to pin V_{SS} to select the SPI-bus connect to pin BBS to select the I^2C-bus
$\overline{\text{TS}}$	6	6	timestamp input (active LOW) with 200 kΩ internal pull-up resistor (R_{PU})
CLKOUT	7	7	clock output (open-drain)
V_{SS}	8	8	ground supply voltage
n.c.	9 to 16	9 to 12	not connected; do not connect; do not use as feed through
$\overline{\text{INT}}$	17	13	interrupt output (open-drain; active LOW)
BBS	18	14	output voltage (battery backed)
V_{BAT}	19	15	battery supply voltage (backup) connect to V_{SS} if battery switch over is not used
V_{DD}	20	16	supply voltage

8. Functional description

The PCF2129 is a Real Time Clock (RTC) and calendar with an on-chip Temperature Compensated Crystal (Xtal) Oscillator (TCXO) and a 32.768 kHz quartz crystal integrated into the same package (see Section 8.3.3).

Address and data are transferred by a selectable 400 kHz Fast-mode I^{2}C-bus or a 3 line SPI-bus with separate data input and output (see Section 9). The maximum speed of the SPI-bus is 6.5 Mbit/s.

The PCF2129 has a backup battery input pin and backup battery switch-over circuit which monitors the main power supply. The backup battery switch-over circuit automatically switches to the backup battery when a power failure condition is detected (see Section 8.5.1). Accurate timekeeping is maintained even when the main power supply is interrupted.

A battery low detection circuit monitors the status of the battery (see Section 8.5.2). When the battery voltage drops below a certain threshold value, a flag is set to indicate that the battery must be replaced soon. This ensures the integrity of the data during periods of battery backup.

8.1 Register overview

The PCF2129 contains an auto-incrementing address register: the built-in address register will increment automatically after each read or write of a data byte up to the register 1Bh. After register 1Bh, the auto-incrementing will wrap around to address 00h (see Figure 5).

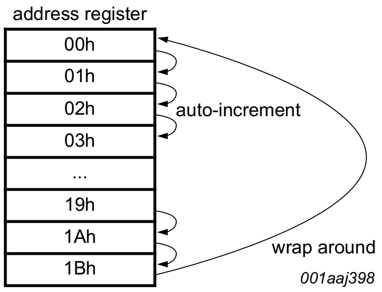


Fig 5. Handling address registers

- The first three registers (memory address 00h, 01h, and 02h) are used as control registers (see Section 8.2).
- The memory addresses 03h through to 09h are used as counters for the clock function (seconds up to years). The date is automatically adjusted for months with fewer than 31 days, including corrections for leap years. The clock can operate in 12-hour mode with an AM/PM indication or in 24-hour mode (see Section 8.8).
- The registers at addresses 0Ah through 0Eh define the alarm function. It can be selected that an interrupt is generated when an alarm event occurs (see Section 8.9).
- The register at address 0Fh defines the temperature measurement period and the clock out mode. The temperature measurement can be selected from every 4 minutes (default) down to every 30 seconds (see Table 14). CLKOUT frequencies of

32.768 kHz (default) down to 1 Hz for use as system clock, microcontroller clock, and so on, can be chosen (see Table 15).

- The registers at addresses 10h and 11h are used for the watchdog timer functions. The watchdog timer has four selectable source clocks allowing for timer periods from less than 1 ms to greater than 4 hours (see Table 52). An interrupt is generated when the watchdog times out.
- The registers at addresses 12h to 18h are used for the timestamp function. When the trigger event happens, the actual time is saved in the timestamp registers (see Section 8.11).
- The register at address 19h is used for the correction of the crystal aging effect (see Section 8.4.1).
- The registers at addresses 1Ah and 1Bh are for internal use only.
- The registers Seconds, Minutes, Hours, Days, Months, and Years are all coded in Binary Coded Decimal (BCD) format to simplify application use. Other registers are either bit-wise or standard binary.

When one of the RTC registers is written or read, the content of all counters is temporarily frozen. This prevents a faulty writing or reading of the clock and calendar during a carry condition (see Section 8.8.8).

Table 5. Register overview

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Address	Register name	Bit								Reset value	Reference
		7	6	5	4	3	2	1	0		
Control registers											
00h	Control_1	EXT_ TEST	T	STOP	TSF1	POR_ OVRD	12_24	MI	SI	0000 1000	Table 7 on page 10
01h	Control_2	MSF	WDTF	TSF2	AF	T	TSIE	AIE	T	0000 0000	Table 9 on page 11
02h	Control_3	PWRMNG[2:0]			BTSE	BF	BLF	BIE	BLIE	0000 0000	Table 11 on page 12
Time and date registers											
03h	Seconds	OSF	SECONDS (0 to 59)							1XXX XXXX	Table 22 on page 25
04h	Minutes	-	MINUTES (0 to 59)							- XXX XXXX	Table 25 on page 26
05h	Hours	-	-	AMPM	HOURS (1 to 12) in 12-hour mode					- - XX XXXX	Table 27 on page 27
				HOURS (0 to 23) in 24-hour mode						- - XX XXXX	
06h	Days	-	-	DAYS (1 to 31)						- - XX XXXX	Table 29 on page 27
07h	Weekdays	-	-	-	-	-	WEEKDAYS (0 to 6)			- - - - - XXX	Table 31 on page 28
08h	Months	-	-	-	MONTHS (1 to 12)					- - - X XXXX	Table 34 on page 29
09h	Years	YEARS (0 to 99)								XXXX XXXX	Table 37 on page 30
Alarm registers											
0Ah	Second_alarm	AE_S	SECOND_ALARM (0 to 59)							1XXX XXXX	Table 39 on page 33
0Bh	Minute_alarm	AE_M	MINUTE_ALARM (0 to 59)							1XXX XXXX	Table 41 on page 33
0Ch	Hour_alarm	AE_H	-	AMPM	HOUR_ALARM (1 to 12) in 12-hour mode					1 - XX XXXX	Table 43 on page 34
				HOUR_ALARM (0 to 23) in 24-hour mode						1 - XX XXXX	
0Dh	Day_alarm	AE_D	-	DAY_ALARM (1 to 31)						1 - XX XXXX	Table 45 on page 34
0Eh	Weekday_alarm	AE_W	-	-	-	-	WEEKDAY_ALARM (0 to 6)			1 - - - - XXX	Table 47 on page 35
CLKOUT control register											
0Fh	CLKOUT_ctl	TCR[1:0]		OTPR	-	-	COF[2:0]			00X - - 000	Table 13 on page 12
Watchdog registers											
10h	Watchdg_tim_ctl	WD_CD	T	TI_TP	-	-	-	TF[1:0]		000 - - - 11	Table 49 on page 36
11h	Watchdg_tim_val	WATCHDG_TIM_VAL[7:0]								XXXX XXXX	Table 51 on page 36
Timestamp registers											
12h	Timestp_ctl	TSM	TSOFF	-	1_O_16_TIMESTP[4:0]					00 - X XXXX	Table 58 on page 41

Table 5. Register overview *…continued*

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Address	Register name	Bit								Reset value	Reference
		7	6	5	4	3	2	1	0		
13h	Sec_timestp	-	SECOND_TIMESTP (0 to 59)							- XXX XXXX	Table 60 on page 41
14h	Min_timestp	-	MINUTE_TIMESTP (0 to 59)							- XXX XXXX	Table 62 on page 42
15h	Hour_timestp	-	-	AMPM	HOUR_TIMESTP (1 to 12) in 12-hour mode					- - XX XXXX	Table 64 on page 42
				HOUR_TIMESTP (0 to 23) in 24-hour mode						- - XX XXXX	
16h	Day_timestp	-	-	DAY_TIMESTP (1 to 31)						- - XX XXXX	Table 66 on page 43
17h	Mon_timestp	-	-	-	MONTH_TIMESTP (1 to 12)					- - - X XXXX	Table 68 on page 43
18h	Year_timestp	YEAR_TIMESTP (0 to 99)								XXXX XXXX	Table 70 on page 43
Aging offset register											
19h	Aging_offset	-	-	-	-	AO[3:0]				- - - - 1000	Table 17 on page 14
Internal registers											
1Ah	Internal_reg	-	-	-	-	-	-	-	-	- - - - - - - -	-
1Bh	Internal_reg	-	-	-	-	-	-	-	-	- - - - - - - -	-

8.2 Control registers

The first 3 registers of the PCF2129, with the addresses 00h, 01h, and 02h, are used as control registers.

8.2.1 Register Control_1

Table 6. Control_1 - control and status register 1 (address 00h) bit allocation
Bits labeled as T must always be written with logic 0.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	EXT_ TEST	T	STOP	TSF1	POR_ OVRD	12_24	MI	SI
Reset value	0	0	0	0	1	0	0	0

Table 7. Control_1 - control and status register 1 (address 00h) bit description
Bits labeled as T must always be written with logic 0.

Bit	**Symbol**	**Value**	**Description**	**Reference**
7	EXT_TEST	0	normal mode	Section 8.13
		1	external clock test mode	
6	T	0	unused	-
5	STOP	0	RTC source clock runs	Section 8.14
		1	RTC clock is stopped; RTC divider chain flip-flops are asynchronously set logic 0; CLKOUT at 32.768 kHz, 16.384 kHz, or 8.192 kHz is still available	
4	TSF1	0	no timestamp interrupt generated	Section 8.11.1
		1	flag set when $\overline{\text{TS}}$ input is driven to an intermediate level between power supply and ground; flag must be cleared to clear interrupt	
3	POR_OVRD	0	Power-On Reset Override (PORO) facility disabled; **set logic 0 for normal operation**	Section 8.7.2
		1	Power-On Reset Override (PORO) sequence reception enabled	
2	12_24	0	24-hour mode selected	Table 27, Table 43, Table 64
		1	12-hour mode selected	
1	MI	0	minute interrupt disabled	Section 8.12.1
		1	minute interrupt enabled	
0	SI	0	second interrupt disabled	
		1	second interrupt enabled	

8.2.2 Register Control_2

Table 8. Control_2 - control and status register 2 (address 01h) bit allocation

Bits labeled as T must always be written with logic 0.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	MSF	WDTF	TSF2	AF	T	TSIE	AIE	T
Reset value	0	0	0	0	0	0	0	0

Table 9. Control_2 - control and status register 2 (address 01h) bit description

Bits labeled as T must always be written with logic 0.

Bit	**Symbol**	**Value**	**Description**	**Reference**
7	MSF	0	no minute or second interrupt generated	Section 8.12
		1	flag set when minute or second interrupt generated; flag must be cleared to clear interrupt	
6	WDTF	0	no watchdog timer interrupt or reset generated	Section 8.12.3
		1	flag set when watchdog timer interrupt or reset generated; flag cannot be cleared by command (read-only)	
5	TSF2	0	no timestamp interrupt generated	Section 8.11.1
		1	flag set when $\overline{\text{TS}}$ input is driven to ground; flag must be cleared to clear interrupt	
4	AF	0	no alarm interrupt generated	Section 8.9.6
		1	flag set when alarm triggered; flag must be cleared to clear interrupt	
3	T	0	unused	-
2	TSIE	0	no interrupt generated from timestamp flag	Section 8.12.5
		1	interrupt generated when timestamp flag set	
1	AIE	0	no interrupt generated from the alarm flag	Section 8.12.4
		1	interrupt generated when alarm flag set	
0	T	0	unused	-

8.2.3 Register Control_3

Table 10. Control_3 - control and status register 3 (address 02h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	PWRMNG[2:0]			BTSE	BF	BLF	BIE	BLIE
Reset value	0	0	0	0	0	0	0	0

Table 11. Control_3 - control and status register 3 (address 02h) bit description

Bit	Symbol	Value	Description	Reference
7 to 5	PWRMNG[2:0]	see Table 19	control of the battery switch-over, battery low detection, and extra power fail detection functions	Section 8.5
4	BTSE	0	no timestamp when battery switch-over occurs	Section 8.11.4
		1	time-stamped when battery switch-over occurs	
3	BF	0	no battery switch-over interrupt generated	Section 8.5.1 and Section 8.11.4
		1	flag set when battery switch-over occurs; flag must be cleared to clear interrupt	
2	BLF	0	battery status ok; no battery low interrupt generated	Section 8.5.2
		1	battery status low; flag cannot be cleared by command	
1	BIE	0	no interrupt generated from the battery flag (BF)	Section 8.12.6
		1	interrupt generated when BF is set	
0	BLIE	0	no interrupt generated from battery low flag (BLF)	Section 8.12.7
		1	interrupt generated when BLF is set	

8.3 Register CLKOUT_ctl

Table 12. CLKOUT_ctl - CLKOUT control register (address 0Fh) bit allocation
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	TCR[1:0]		OTPR	-	-	COF[2:0]		
Reset value	0	0	X	-	-	0	0	0

Table 13. CLKOUT_ctl - CLKOUT control register (address 0Fh) bit description
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description
7 to 6	TCR[1:0]	see Table 14	temperature measurement period
5	OTPR	0	no OTP refresh
		1	OTP refresh performed
4 to 3	-	-	unused
2 to 0	COF[2:0]	see Table 15	CLKOUT frequency selection

8.3.1 Temperature compensated crystal oscillator

The frequency of tuning fork quartz crystal oscillators is temperature-dependent. In the PCF2129, the frequency deviation caused by temperature variation is corrected by adjusting the load capacitance of the crystal oscillator.

The load capacitance is changed by switching between two load capacitance values using a modulation signal with a programmable duty cycle. In order to compensate the spread of the quartz parameters every chip is factory calibrated.

The frequency accuracy can be evaluated by measuring the frequency of the square wave signal available at the output pin CLKOUT. However, the selection of f_{CLKOUT} = 32.768 kHz (default value) leads to inaccurate measurements. Accurate frequency measurement occurs when f_{CLKOUT} = 16.384 kHz or lower is selected (see Table 15).

8.3.1.1 Temperature measurement

The PCF2129 has a temperature sensor circuit used to perform the temperature compensation of the frequency. The temperature is measured immediately after power-on and then periodically with a period set by the temperature conversion rate TCR[1:0] in the register CLKOUT_ctl.

Table 14. Temperature measurement period

TCR[1:0]	Temperature measurement period
00 [1]	4 min
01	2 min
10	1 min
11	30 seconds

[1] Default value.

8.3.2 OTP refresh

Each IC is calibrated during production and testing of the device. The calibration parameters are stored on EPROM cells called One Time Programmable (OTP) cells. It is recommended to process an OTP refresh once after the power is up and the oscillator is operating stable. The OTP refresh takes less than 100 ms to complete.

To perform an OTP refresh, bit OTPR has to be cleared (set to logic 0) and then set to logic 1 again.

8.3.3 Clock output

A programmable square wave is available at pin CLKOUT. Operation is controlled by the COF[2:0] control bits in register CLKOUT_ctl. Frequencies of 32.768 kHz (default) down to 1 Hz can be generated for use as system clock, microcontroller clock, charge pump input, or for calibrating the oscillator.

CLKOUT is an open-drain output and enabled at power-on. When disabled, the output is high-impedance.

Table 15. CLKOUT frequency selection

COF[2:0]	CLKOUT frequency (Hz)	Typical duty cycle[1]
000 [2][3]	32768	60 : 40 to 40 : 60
001	16384	50 : 50
010	8192	50 : 50
011	4096	50 : 50
100	2048	50 : 50
101	1024	50 : 50
110	1	50 : 50
111	CLKOUT = high-Z	-

[1] Duty cycle definition: % HIGH-level time : % LOW-level time.

[2] Default value.

[3] The specified accuracy of the RTC can be only achieved with CLKOUT frequencies not equal to 32.768 kHz or if CLKOUT is disabled.

The duty cycle of the selected clock is not controlled, however, due to the nature of the clock generation all but the 32.768 kHz frequencies are 50 : 50.

8.4 Register Aging_offset

Table 16. Aging_offset - crystal aging offset register (address 19h) bit allocation
Bit positions labeled as - are not implemented and return 0 when read.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	-	-	AO[3:0]			
Reset value	-	-	-	-	1	0	0	0

Table 17. Aging_offset - crystal aging offset register (address 19h) bit description
Bit positions labeled as - are not implemented and return 0 when read.

Bit	Symbol	Value	Description
7 to 4	-	-	unused
3 to 0	AO[3:0]	see Table 18	aging offset value

8.4.1 Crystal aging correction

The PCF2129 has an offset register Aging_offset to correct the crystal aging effects[2].

The accuracy of the frequency of a quartz crystal depends on its aging. The aging offset adds an adjustment, positive or negative, in the temperature compensation circuit which allows correcting the aging effect.

At 25 °C, the aging offset bits allow a frequency correction of typically 1 ppm per AO[3:0] value, from –7 ppm to +8 ppm.

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[2] For further information, refer to the application note Ref. 3 "AN11186".

Table 18. Frequency correction at 25 °C, typical

AO[3:0]		ppm
Decimal	Binary	
0	0000	+8
1	0001	+7
2	0010	+6
3	0011	+5
4	0100	+4
5	0101	+3
6	0110	+2
7	0111	+1
8	1000 [1]	0
9	1001	–1
10	1010	–2
11	1011	–3
12	1100	–4
13	1101	–5
14	1110	–6
15	1111	–7

[1] Default value.

8.5 Power management functions

The PCF2129 has two power supplies:

V_{DD} — the main power supply

V_{BAT} — the battery backup supply

Internally, the PCF2129 is operating with the internal operating voltage $V_{oper(int)}$ which is also available as V_{BBS} on the battery backed output voltage pin, BBS. Depending on the condition of the main power supply and the selected power management function, $V_{oper(int)}$ is either on the potential of V_{DD} or V_{BAT} (see Section 8.5.3).

Two power management functions are implemented:

Battery switch-over function — monitoring the main power supply V_{DD} and switching to V_{BAT} in case a power fail condition is detected (see Section 8.5.1).

Battery low detection function — monitoring the status of the battery, V_{BAT} (see Section 8.5.2).

The power management functions are controlled by the control bits PWRMNG[2:0] (see Table 19) in register Control_3 (see Table 11):

Table 19. Power management control bit description

PWRMNG[2:0]	Function
000 [1]	battery switch-over function is enabled in standard mode; battery low detection function is enabled
001	battery switch-over function is enabled in standard mode; battery low detection function is disabled
010	battery switch-over function is enabled in standard mode; battery low detection function is disabled
011	battery switch-over function is enabled in direct switching mode; battery low detection function is enabled
100	battery switch-over function is enabled in direct switching mode; battery low detection function is disabled
101	battery switch-over function is enabled in direct switching mode; battery low detection function is disabled
111 [2]	battery switch-over function is disabled, only one power supply (V_{DD}); battery low detection function is disabled

[1] Default value.

[2] When the battery switch-over function is disabled, the PCF2129 works only with the power supply V_{DD}. V_{BAT} must be put to ground and the battery low detection function is disabled.

8.5.1 Battery switch-over function

The PCF2129 has a backup battery switch-over circuit which monitors the main power supply V_{DD}. When a power failure condition is detected, it automatically switches to the backup battery.

One of two operation modes can be selected:

Standard mode — the power failure condition happens when:
$V_{DD} < V_{BAT}$ AND $V_{DD} < V_{th(sw)bat}$
$V_{th(sw)bat}$ is the battery switch threshold voltage. Typical value is 2.5 V. The battery switch-over in standard mode works only for $V_{DD} > 2.5$ V

Direct switching mode — the power failure condition happens when $V_{DD} < V_{BAT}$. Direct switching from V_{DD} to V_{BAT} without requiring V_{DD} to drop below $V_{th(sw)bat}$

When a power failure condition occurs and the power supply switches to the battery, the following sequence occurs:

1. The battery switch flag BF (register Control_3) is set logic 1.
2. An interrupt is generated if the control bit BIE (register Control_3) is enabled (see Section 8.12.6).
3. If the control bit BTSE (register Control_3) is logic 1, the timestamp registers store the time and date when the battery switch occurred (see Section 8.11.4).
4. The battery switch flag BF is cleared by command; it must be cleared to clear the interrupt.

The interface is disabled in battery backup operation:

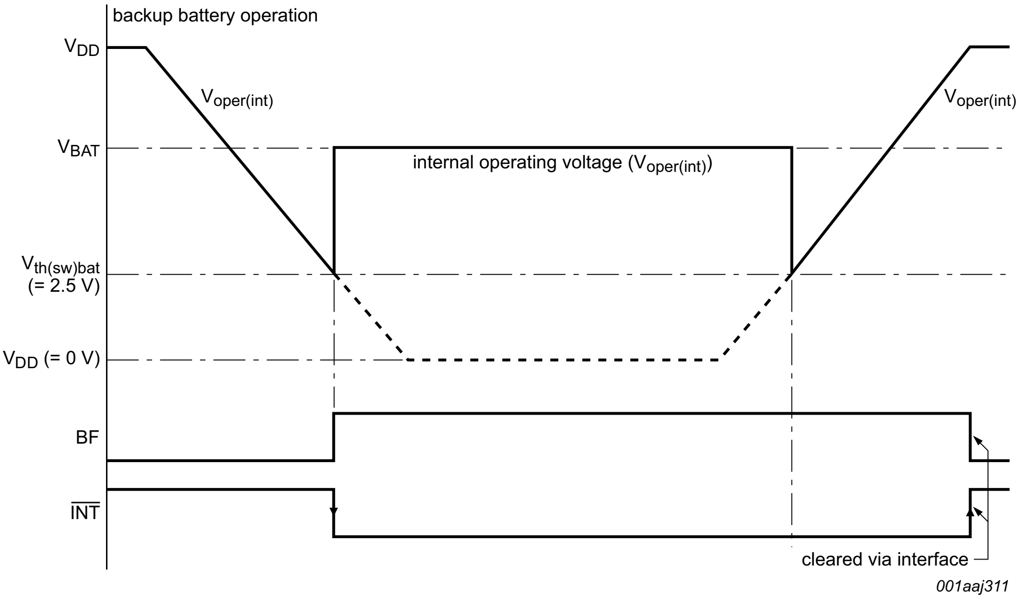
- Interface inputs are not recognized, preventing extraneous data being written to the device
- Interface outputs are high-impedance

For further information about I^2C-bus communication and battery backup operation, see Section 9.3 on page 56.

8.5.1.1 Standard mode

If $V_{DD} > V_{BAT}$ OR $V_{DD} > V_{th(sw)bat}$: $V_{oper(int)}$ is at V_{DD} potential.

If $V_{DD} < V_{BAT}$ AND $V_{DD} < V_{th(sw)bat}$: $V_{oper(int)}$ is at V_{BAT} potential.



$V_{th(sw)bat}$ is the battery switch threshold voltage. Typical value is 2.5 V. In standard mode, the battery switch-over works only for $V_{DD} > 2.5$ V.

V_{DD} may be lower than V_{BAT} (for example $V_{DD} = 3$ V, $V_{BAT} = 4.1$ V).

Fig 6. Battery switch-over behavior in standard mode with bit BIE set logic 1 (enabled)

8.5.1.2 Direct switching mode

If $V_{DD} > V_{BAT}$: $V_{oper(int)}$ is at V_{DD} potential.

If $V_{DD} < V_{BAT}$: $V_{oper(int)}$ is at V_{BAT} potential.

The direct switching mode is useful in systems where V_{DD} is always higher than V_{BAT}. This mode is not recommended if the V_{DD} and V_{BAT} values are similar (for example, V_{DD} = 3.3 V, $V_{BAT} \geq 3.0$ V). In direct switching mode, the power consumption is reduced compared to the standard mode because the monitoring of V_{DD} and $V_{th(sw)bat}$ is not performed.

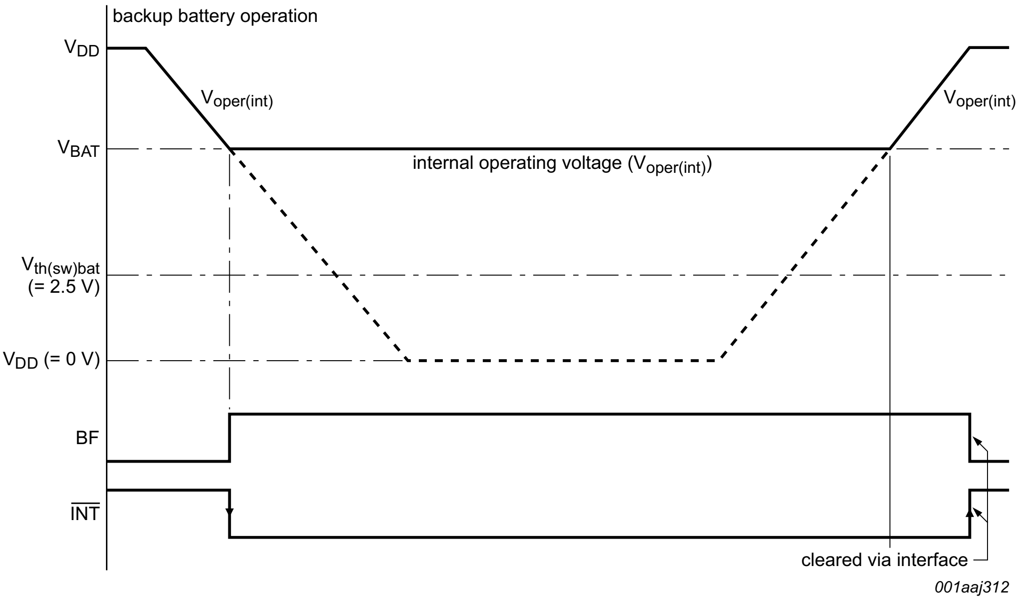


Fig 7. Battery switch-over behavior in direct switching mode with bit BIE set logic 1 (enabled)

8.5.1.3 Battery switch-over disabled: only one power supply (V_{DD})

When the battery switch-over function is disabled:

- The power supply is applied on the V_{DD} pin
- The V_{BAT} pin must be connected to ground
- $V_{oper(int)}$ is at V_{DD} potential
- The battery flag (BF) is always logic 0

8.5.1.4 Battery switch-over architecture

The architecture of the battery switch-over circuit is shown in Figure 8.

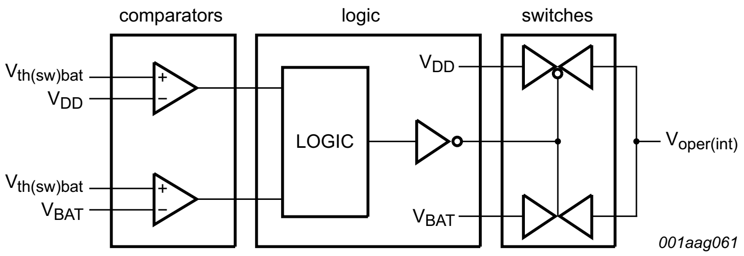


Fig 8. Battery switch-over circuit, simplified block diagram

$V_{oper(int)}$ is at V_{DD} or V_{BAT} potential.

Remark: It has to be assured that there are decoupling capacitors on the pins V_{DD}, V_{BAT}, and BBS.

8.5.2 Battery low detection function

The PCF2129 has a battery low detection circuit which monitors the status of the battery V_{BAT}.

When V_{BAT} drops below the threshold value $V_{th(bat)low}$ (typically 2.5 V), the BLF flag (register Control_3) is set to indicate that the battery is low and that it must be replaced. Monitoring of the battery voltage also occurs during battery operation.

An unreliable battery cannot prevent that the supply voltage drops below V_{low} (typical 1.2 V) and with that the data integrity gets lost. (For further information about V_{low} see Section 8.6.)

When V_{BAT} drops below the threshold value $V_{th(bat)low}$, the following sequence occurs (see Figure 9):

1. The battery low flag BLF is set logic 1.
2. An interrupt is generated if the control bit BLIE (register Control_3) is enabled (see Section 8.12.7).
3. The flag BLF remains logic 1 until the battery is replaced. BLF cannot be cleared by command. It is automatically cleared by the battery low detection circuit when the battery is replaced or when the voltage rises again above the threshold value. This could happen if a super capacitor is used as a backup source and the main power is applied again.

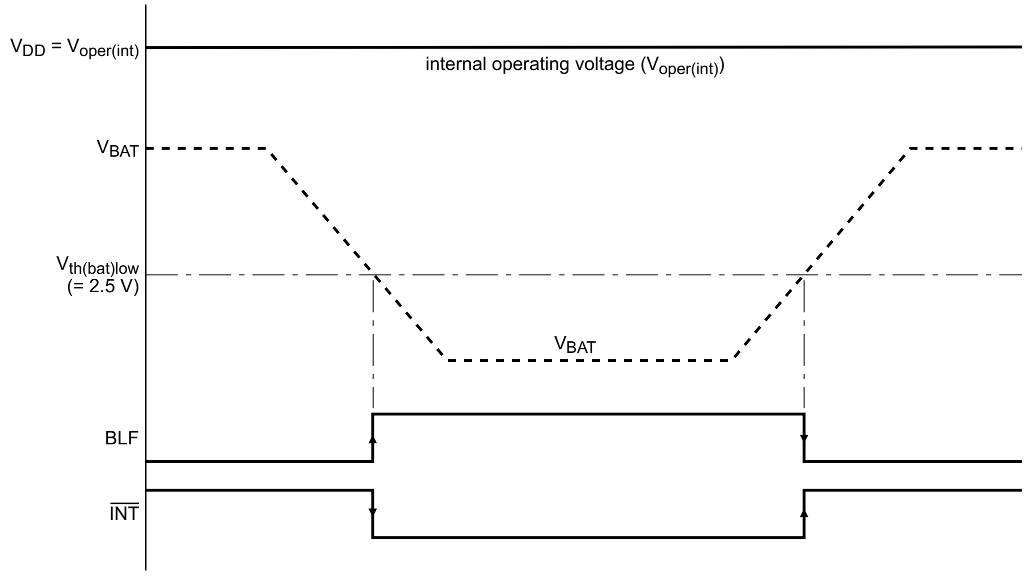


Fig 9. Battery low detection behavior with bit BLIE set logic 1 (enabled)

8.5.3 Battery backup supply

The V_{BBS} voltage on the output pin BBS is at the same potential as the internal operating voltage $V_{oper(int)}$, depending on the selected battery switch-over function mode:

Table 20. Output pin BBS

Battery switch-over function mode	Conditions	Potential of $V_{oper(int)}$ and V_{BBS}
standard	$V_{DD} > V_{BAT}$ OR $V_{DD} > V_{th(sw)bat}$	V_{DD}
	$V_{DD} < V_{BAT}$ AND $V_{DD} < V_{th(sw)bat}$	V_{BAT}
direct switching	$V_{DD} > V_{BAT}$	V_{DD}
	$V_{DD} < V_{BAT}$	V_{BAT}
disabled	only V_{DD} available, V_{BAT} must be put to ground	V_{DD}

The output pin BBS can be used as a supply for external devices with battery backup needs, such as SRAM (see Ref. 3 “AN11186”). For this case, Figure 10 shows the typical driving capability when V_{BBS} is driven from V_{DD}.

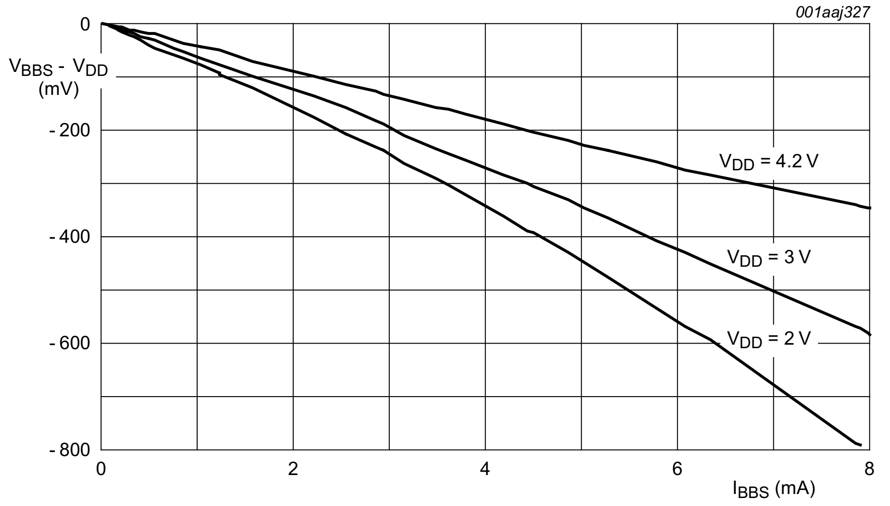
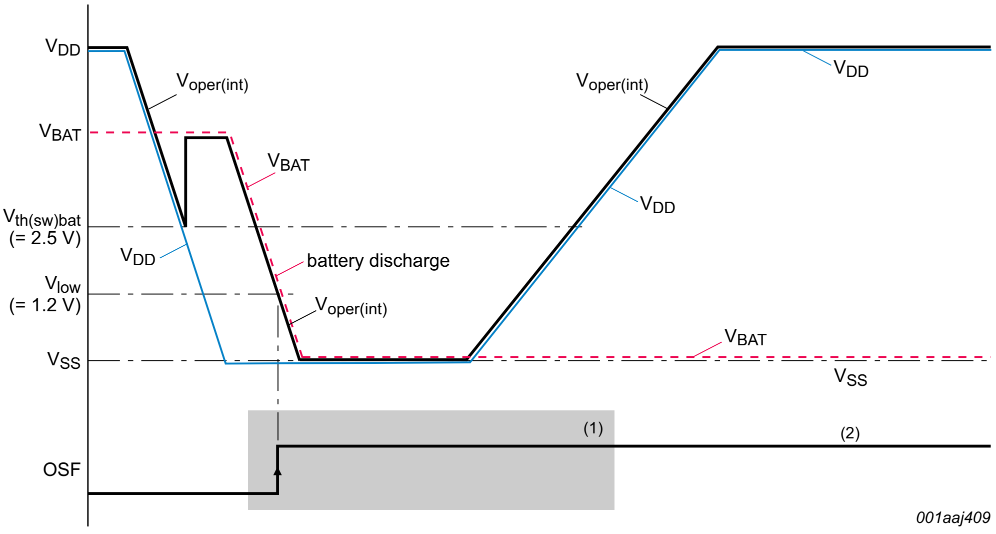


Fig 10. Typical driving capability of V_{BBS}: ($V_{BBS} - V_{DD}$) with respect to the output load current I_{BBS}

8.6 Oscillator stop detection function

The PCF2129 has an on-chip oscillator detection circuit which monitors the status of the oscillation: whenever the oscillation stops, a reset occurs and the oscillator stop flag OSF (in register Seconds) is set logic 1.

- **Power-on:**
  a. The oscillator is not running, the chip is in reset (OSF is logic 1).
  b. When the oscillator starts running and is stable after power-on, the chip exits from reset.
  c. The flag OSF is still logic 1 and can be cleared (OSF set logic 0) by command.
- **Power supply failure:**
  a. When the power supply of the chip drops below a certain value (V_{low}), typically 1.2 V, the oscillator stops running and a reset occurs.
  b. When the power supply returns to normal operation, the oscillator starts running again, the chip exits from reset.
  c. The flag OSF is still logic 1 and can be cleared (OSF set logic 0) by command.



(1) Theoretical state of the signals since there is no power.

(2) The oscillator stop flag (OSF), set logic 1, indicates that the oscillation has stopped and a reset has occurred since the flag was last cleared (OSF set logic 0). In this case, the integrity of the clock information is not guaranteed. The OSF flag is cleared by command.

Fig 11. Power failure event due to battery discharge: reset occurs

8.7 Reset function

The PCF2129 has a Power-On Reset (POR) and a Power-On Reset Override (PORO) function implemented.

8.7.1 Power-On Reset (POR)

The POR is active whenever the oscillator is stopped. The oscillator is considered to be stopped during the time between power-on and stable crystal resonance (see Figure 12). This time may be in the range of 200 ms to 2 s depending on temperature and supply voltage. Whenever an internal reset occurs, the oscillator stop flag is set (OSF set logic 1).

The OTP refresh (see Section 8.3.2 on page 13) should ideally be executed as the first instruction after start-up and also after a reset due to an oscillator stop.

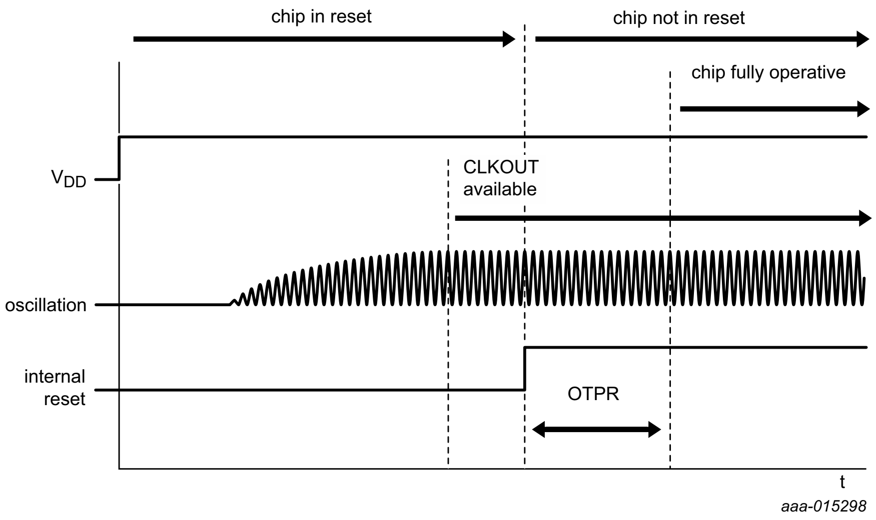


Fig 12. Dependency between POR and oscillator

After POR, the following mode is entered:

- 32.768 kHz CLKOUT active
- Power-On Reset Override (PORO) available to be set
- 24-hour mode is selected
- Battery switch-over is enabled
- Battery low detection is enabled

The register values after power-on are shown in Table 5 on page 8.

8.7.2 Power-On Reset Override (PORO)

The POR duration is directly related to the crystal oscillator start-up time. Due to the long start-up times experienced by these types of circuits, a mechanism has been built in to disable the POR and therefore speed up the on-board test of the device.

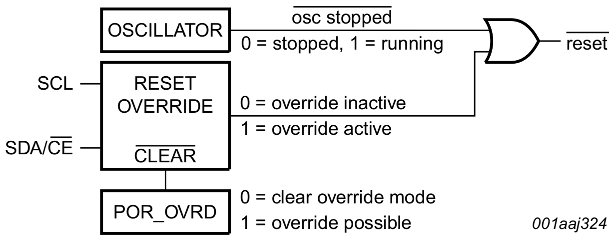


Fig 13. Power-On Reset (POR) system

The setting of the PORO mode requires that POR_OVRD in register Control_1 is set logic 1 and that the signals at the interface pins SDA/$\overline{\text{CE}}$ and SCL are toggled as illustrated in Figure 14. All timings shown are required minimum.

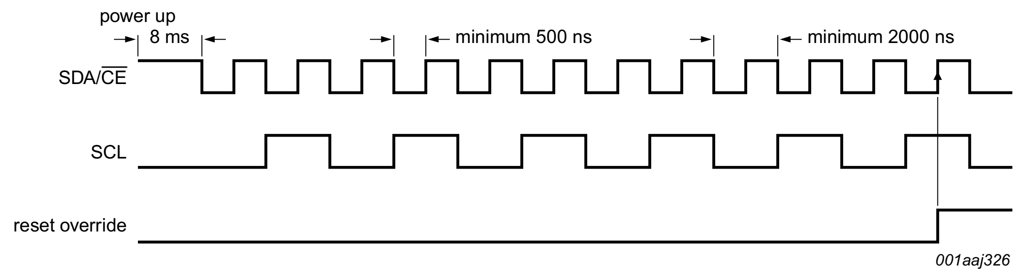


Fig 14. Power-On Reset Override (PORO) sequence, valid for both I²C-bus and SPI-bus

Once the override mode is entered, the device is immediately released from the reset state and the set-up operation can commence.

The PORO mode is cleared by writing logic 0 to POR_OVRD. POR_OVRD must be logic 1 before a re-entry into the override mode is possible. Setting POR_OVRD logic 0 during normal operation has no effect except to prevent accidental entry into the PORO mode.

8.8 Time and date function

Most of these registers are coded in the Binary Coded Decimal (BCD) format.

8.8.1 Register Seconds

Table 21. Seconds - seconds and clock integrity register (address 03h) bit allocation

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	OSF	SECONDS (0 to 59)						
Reset value	1	X	X	X	X	X	X	X

Table 22. Seconds - seconds and clock integrity register (address 03h) bit description

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	OSF	0	-	clock integrity is guaranteed
		1	-	clock integrity is not guaranteed: oscillator has stopped and chip reset has occurred since flag was last cleared
6 to 4	SECONDS	0 to 5	ten’s place	actual seconds coded in BCD format
3 to 0		0 to 9	unit place	

Table 23. Seconds coded in BCD format

Seconds value in decimal	Upper-digit (ten’s place)			Digit (unit place)			
	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
00	0	0	0	0	0	0	0
01	0	0	0	0	0	0	1
02	0	0	0	0	0	1	0
:	:	:	:	:	:	:	:
09	0	0	0	1	0	0	1
10	0	0	1	0	0	0	0
:	:	:	:	:	:	:	:
58	1	0	1	1	0	0	0
59	1	0	1	1	0	0	1

8.8.2 Register Minutes

Table 24. Minutes - minutes register (address 04h) bit allocation
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	MINUTES (0 to 59)						
Reset value	-	X	X	X	X	X	X	X

Table 25. Minutes - minutes register (address 04h) bit description
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	-	-	-	unused
6 to 4	MINUTES	0 to 5	ten’s place	actual minutes coded in BCD format
3 to 0		0 to 9	unit place	

8.8.3 Register Hours

Table 26. Hours - hours register (address 05h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	-	-	AMPM	HOURS (1 to 12) in 12-hour mode				
			HOURS (0 to 23) in 24-hour mode					
Reset value	-	-	X	X	X	X	X	X

Table 27. Hours - hours register (address 05h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**Symbol**	**Value**	**Place value**	**Description**
7 to 6	-	-	-	unused
12-hour mode[1]				
5	AMPM	0	-	indicates AM
		1	-	indicates PM
4	HOURS	0 to 1	ten's place	actual hours coded in BCD format when in 12-hour mode
3 to 0		0 to 9	unit place	
24-hour mode[1]				
5 to 4	HOURS	0 to 2	ten's place	actual hours coded in BCD format when in 24-hour mode
3 to 0		0 to 9	unit place	

[1] Hour mode is set by the bit 12_24 in register Control_1 (see Table 7).

8.8.4 Register Days

Table 28. Days - days register (address 06h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	-	-	DAYS (1 to 31)					
Reset value	-	-	X	X	X	X	X	X

Table 29. Days - days register (address 06h) bit description

Bit	**Symbol**	**Value**	**Place value**	**Description**
7 to 6	-	-	-	unused
5 to 4	DAYS[1]	0 to 3	ten's place	actual day coded in BCD format
3 to 0		0 to 9	unit place	

[1] If the year counter contains a value which is exactly divisible by 4, including the year 00, the RTC compensates for leap years by adding a 29th day to February.

8.8.5 Register Weekdays

Table 30. Weekdays - weekdays register (address 07h) bit allocation
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	-	-	-	WEEKDAYS (0 to 6)		
Reset value	-	-	-	-	-	X	X	X

Table 31. Weekdays - weekdays register (address 07h) bit description
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description
7 to 3	-	-	unused
2 to 0	WEEKDAYS	0 to 6	actual weekday value, see Table 32

Although the association of the weekdays counter to the actual weekday is arbitrary, the PCF2129 assumes that Sunday is 000 and Monday is 001 for the purpose of determining the increment for calendar weeks.

Table 32. Weekday assignments

Day[1]	Bit		
	2	**1**	**0**
Sunday	0	0	0
Monday	0	0	1
Tuesday	0	1	0
Wednesday	0	1	1
Thursday	1	0	0
Friday	1	0	1
Saturday	1	1	0

[1] Definition may be reassigned by the user.

8.8.6 Register Months

Table 33. Months - months register (address 08h) bit allocation
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	-	-	-	MONTHS (1 to 12)				
Reset value	-	-	-	X	X	X	X	X

Table 34. Months - months register (address 08h) bit description
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 5	-	-	-	unused
4	MONTHS	0 to 1	ten’s place	actual month coded in BCD format, see Table 35
3 to 0		0 to 9	unit place	

Table 35. Month assignments in BCD format

Month	Upper-digit (ten’s place)	Digit (unit place)			
	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
January	0	0	0	0	1
February	0	0	0	1	0
March	0	0	0	1	1
April	0	0	1	0	0
May	0	0	1	0	1
June	0	0	1	1	0
July	0	0	1	1	1
August	0	1	0	0	0
September	0	1	0	0	1
October	1	0	0	0	0
November	1	0	0	0	1
December	1	0	0	1	0

8.8.7 Register Years

Table 36. Years - years register (address 09h) bit allocation
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	YEARS (0 to 99)							
Reset value	X	X	X	X	X	X	X	X

Table 37. Years - years register (address 09h) bit description
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 4	YEARS	0 to 9	ten's place	actual year coded in BCD format
3 to 0		0 to 9	unit place	

8.8.8 Setting and reading the time

Figure 15 shows the data flow and data dependencies starting from the 1 Hz clock tick.

During read/write operations, the time counting circuits (memory locations 03h through 09h) are blocked.

This prevents

- Faulty reading of the clock and calendar during a carry condition
- Incrementing the time registers during the read cycle

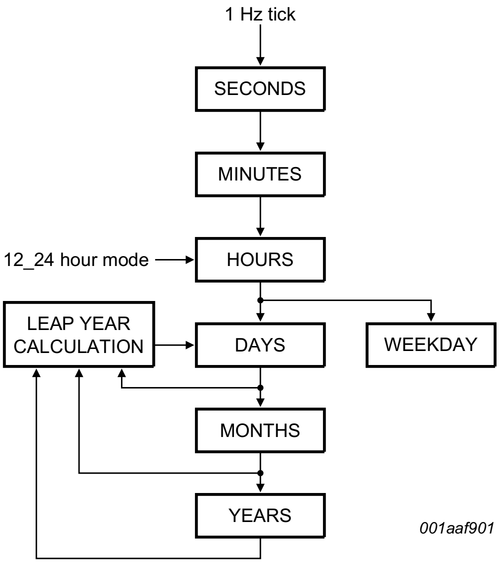


Fig 15. Data flow of the time function

After this read/write access is completed, the time circuit is released again. Any pending request to increment the time counters that occurred during the read/write access is serviced. A maximum of 1 request can be stored; therefore, all accesses must be completed within 1 second (see Figure 16).

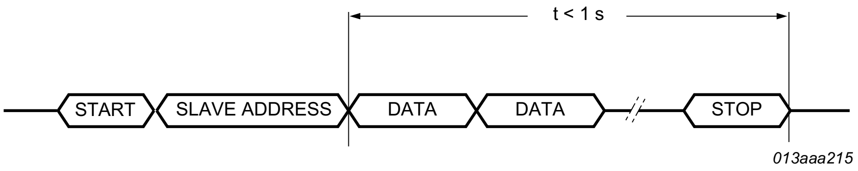


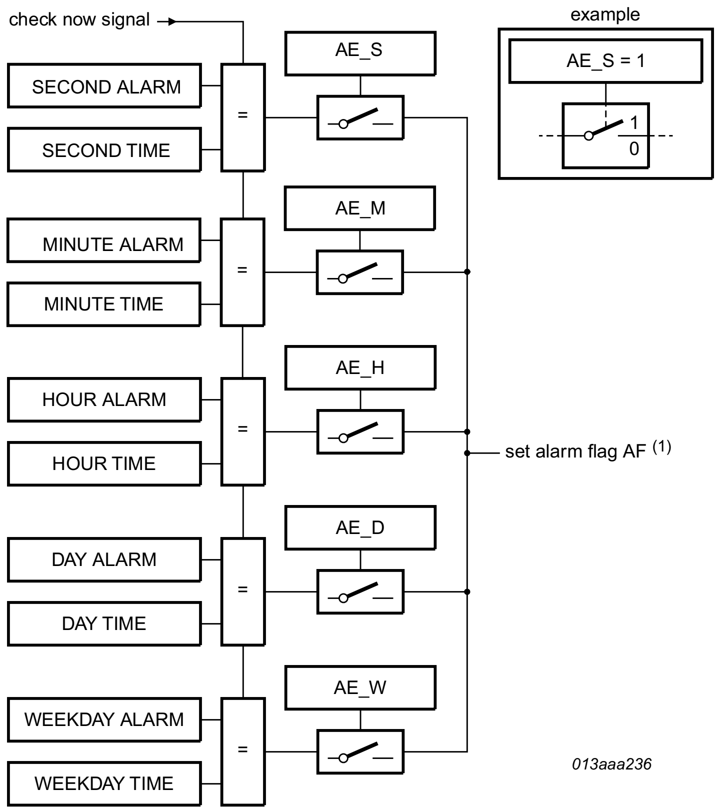
Fig 16. Access time for read/write operations

As a consequence of this method, it is very important to make a read or write access in one go. That is, setting or reading seconds through to years should be made in one single access. Failing to comply with this method could result in the time becoming corrupted.

As an example, if the time (seconds through to hours) is set in one access and then in a second access the date is set, it is possible that the time may increment between the two accesses. A similar problem exists when reading. A roll-over may occur between reads thus giving the minutes from one moment and the hours from the next. Therefore it is advised to read all time and date registers in one access.

8.9 Alarm function

When one or more of the alarm bit fields are loaded with a valid second, minute, hour, day, or weekday and its corresponding alarm enable bit (AE_x) is logic 0, then that information is compared with the actual second, minute, hour, day, and weekday (see Figure 17).



(1) Only when all enabled alarm settings are matching.

Fig 17. Alarm function block diagram

The generation of interrupts from the alarm function is described in Section 8.12.4.

8.9.1 Register Second_alarm

Table 38. Second_alarm - second alarm register (address 0Ah) bit allocation
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	AE_S	SECOND_ALARM (0 to 59)						
Reset value	1	X	X	X	X	X	X	X

Table 39. Second_alarm - second alarm register (address 0Ah) bit description

Bit	Symbol	Value	Place value	Description
7	AE_S	0	-	second alarm is enabled
		1	-	second alarm is disabled
6 to 4	SECOND_ALARM	0 to 5	ten’s place	second alarm information coded in BCD format
3 to 0		0 to 9	unit place	

8.9.2 Register Minute_alarm

Table 40. Minute_alarm - minute alarm register (address 0Bh) bit allocation
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	AE_M	MINUTE_ALARM (0 to 59)						
Reset value	1	X	X	X	X	X	X	X

Table 41. Minute_alarm - minute alarm register (address 0Bh) bit description
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	AE_M	0	-	minute alarm is enabled
		1	-	minute alarm is disabled
6 to 4	MINUTE_ALARM	0 to 5	ten’s place	minute alarm information coded in BCD format
3 to 0		0 to 9	unit place	

8.9.3 Register Hour_alarm

Table 42. Hour_alarm - hour alarm register (address 0Ch) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_H	-	AMPM	HOUR_ALARM (1 to 12) in 12-hour mode				
			HOUR_ALARM (0 to 23) in 24-hour mode					
Reset value	1	-	X	X	X	X	X	X

Table 43. Hour_alarm - hour alarm register (address 0Ch) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	AE_H	0	-	hour alarm is enabled
		1	-	hour alarm is disabled
6	-	-	-	unused
12-hour mode[1]				
5	AMPM	0	-	indicates AM
		1	-	indicates PM
4	HOUR_ALARM	0 to 1	ten’s place	hour alarm information coded in BCD format when in 12-hour mode
3 to 0		0 to 9	unit place	
24-hour mode[1]				
5 to 4	HOUR_ALARM	0 to 2	ten’s place	hour alarm information coded in BCD format when in 24-hour mode
3 to 0		0 to 9	unit place	

[1] Hour mode is set by the bit 12_24 in register Control_1.

8.9.4 Register Day_alarm

Table 44. Day_alarm - day alarm register (address 0Dh) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_D	-	DAY_ALARM (1 to 31)					
Reset value	1	-	X	X	X	X	X	X

Table 45. Day_alarm - day alarm register (address 0Dh) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	AE_D	0	-	day alarm is enabled
		1	-	day alarm is disabled
6	-	-	-	unused
5 to 4	DAY_ALARM	0 to 3	ten’s place	day alarm information coded in BCD format
3 to 0		0 to 9	unit place	

8.9.5 Register Weekday_alarm

Table 46. Weekday_alarm - weekday alarm register (address 0Eh) bit allocation
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	AE_W	-	-	-	-	WEEKDAY_ALARM (0 to 6)		
Reset value	1	-	-	-	-	X	X	X

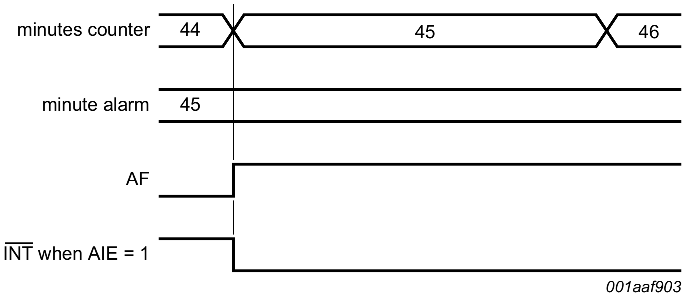
Table 47. Weekday_alarm - weekday alarm register (address 0Eh) bit description
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**Symbol**	**Value**	**Description**
7	AE_W	0	weekday alarm is enabled
		1	weekday alarm is disabled
6 to 3	-	-	unused
2 to 0	WEEKDAY_ALARM	0 to 6	weekday alarm information

8.9.6 Alarm flag

When all enabled comparisons first match, the alarm flag AF (register Control_2) is set. AF remains set until cleared by command. Once AF has been cleared, it will only be set again when the time increments to match the alarm condition once more. For clearing the flags, see Section 8.10.5

Alarm registers which have their alarm enable bit AE_x at logic 1 are ignored.



Example where only the minute alarm is used and no other interrupts are enabled.

Fig 18. Alarm flag timing diagram

8.10 Timer functions

The PCF2129 has a watchdog timer function. The timer can be switched on and off by using the control bit WD_CD in the register Watchdg_tim_ctl.

The watchdog timer has four selectable source clocks. It can, for example, be used to detect a microcontroller with interrupt and reset capability which is out of control (see Section 8.10.3)

To control the timer function and timer output, the registers Control_2, Watchdg_tim_ctl, and Watchdg_tim_val are used.

8.10.1 Register Watchdg_tim_ctl

Table 48. Watchdg_tim_ctl - watchdog timer control register (address 10h) bit allocation
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0.

Bit	7	6	5	4	3	2	1	0
Symbol	WD_CD	T	TI_TP	-	-	-	TF[1:0]	
Reset value	0	0	0	-	-	-	1	1

Table 49. Watchdg_tim_ctl - watchdog timer control register (address 10h) bit description
Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0.

Bit	Symbol	Value	Description
7	WD_CD	0	watchdog timer disabled
		1	watchdog timer enabled; the interrupt pin $\overline{INT}$ is activated when timed out
6	T	0	unused
5	TI_TP	0	the interrupt pin $\overline{INT}$ is configured to generate a permanent active signal when MSF is set
		1	the interrupt pin $\overline{INT}$ is configured to generate a pulsed signal when MSF flag is set (see Figure 21)
4 to 2	-	-	unused
1 to 0	TF[1:0]		timer source clock for watchdog timer
		00	4.096 kHz
		01	64 Hz
		10	1 Hz
		11	$\frac{1}{60}$ Hz

8.10.2 Register Watchdg_tim_val

Table 50. Watchdg_tim_val - watchdog timer value register (address 11h) bit allocation
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	WATCHDG_TIM_VAL[7:0]							
Reset value	X	X	X	X	X	X	X	X

Table 51. Watchdg_tim_val - watchdog timer value register (address 11h) bit description
Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description
7 to 0	WATCHDG_TIM_VAL[7:0]	00 to FF	timer period in seconds: $TimerPeriod = \frac{n}{SourceClockFrequency}$ where n is the timer value

Table 52. Programmable watchdog timer

TF[1:0]	Timer source clock frequency	Units	Minimum timer period (n = 1)	Units	Maximum timer period (n = 255)	Units
00	4.096	kHz	244	µs	62.256	ms
01	64	Hz	15.625	ms	3.984	s
10	1	Hz	1	s	255	s
11	$\frac{1}{60}$	Hz	60	s	15300	s

8.10.3 Watchdog timer function

The watchdog timer function is enabled or disabled by the WD_CD bit of the register Watchdg_tim_ctl (see Table 49).

The 2 bits TF[1:0] in register Watchdg_tim_ctl determine one of the four source clock frequencies for the watchdog timer: 4.096 kHz, 64 Hz, 1 Hz, or $\frac{1}{60}$ Hz (see Table 52).

When the watchdog timer function is enabled, the 8-bit timer in register Watchdg_tim_val determines the watchdog timer period (see Table 52).

The watchdog timer counts down from the software programmed 8-bit binary value n in register Watchdg_tim_val. When the counter reaches 1, the watchdog timer flag WDTF (register Control_2) is set logic 1 and an interrupt is generated.

The counter does not automatically reload.

When WD_CD is logic 0 (watchdog timer disabled) and the Microcontroller Unit (MCU) loads a watchdog timer value n:

- the flag WDTF is reset
- $\overline{\text{INT}}$ is cleared
- the watchdog timer starts again

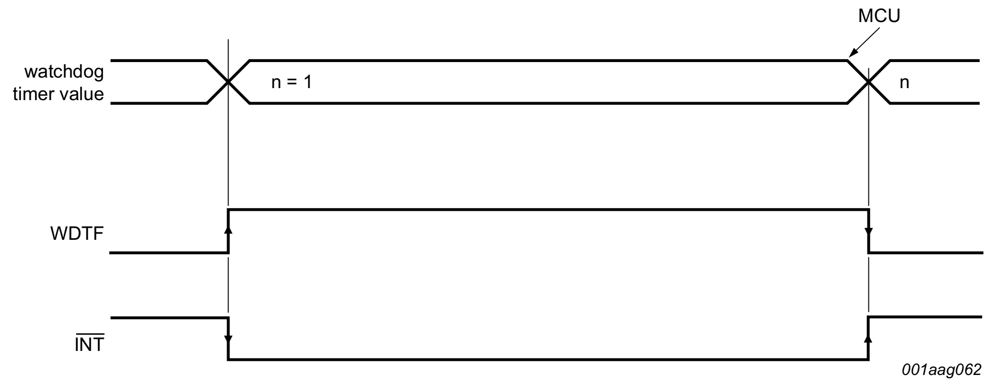
Loading the counter with 0 will:

- reset the flag WDTF
- clear $\overline{\text{INT}}$
- stop the watchdog timer

Remark: WDTF is read only and cannot be cleared by command. WDTF can be cleared by:

- loading a value in register Watchdg_tim_val
- reading of the register Control_2

Writing a logic 0 or logic 1 to WDTF has no effect.



Counter reached 1, WDTF is logic 1, and an interrupt is generated.

Fig 19. WD_CD set logic 1: watchdog activates an interrupt when timed out

- When the watchdog timer counter reaches 1, the watchdog timer flag WDTF is set logic 1
- When a minute or second interrupt occurs, the minute/second flag MSF is set logic 1 (see Section 8.12.1).

8.10.4 Pre-defined timers: second and minute interrupt

PCF2129 has two pre-defined timers which are used to generate an interrupt either once per second or once per minute (see Section 8.12.1). The pulse generator for the minute or second interrupt operates from an internal 64 Hz clock. It is independent of the watchdog timer. Each of these timers can be enabled by the bits SI (second interrupt) and MI (minute interrupt) in register Control_1.

8.10.5 Clearing flags

The flags MSF, AF, and TSFx can be cleared by command. To prevent one flag being overwritten while clearing another, a logic AND is performed during the write access. A flag is cleared by writing logic 0 while a flag is not cleared by writing logic 1. Writing logic 1 results in the flag value remaining unchanged.

Two examples are given for clearing the flags. Clearing a flag is made by a write command:

- Bits labeled with - must be written with their previous values
- Bits labeled with T have to be written with logic 0
- WDTF is read only and has to be written with logic 0

Repeatedly rewriting these bits has no influence on the functional behavior.

Table 53. Flag location in register Control_2

Register	**Bit**							
	7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Control_2	MSF	WDTF	TSF2	AF	T	-	-	T

Table 54. Example values in register Control_2

Register	Bit							
	7	6	5	4	3	2	1	0
Control_2	1	0	1	1	0	0	0	0

The following tables show what instruction must be sent to clear the appropriate flag.

Table 55. Example to clear only AF (bit 4)

Register	Bit							
	7	6	5	4	3	2	1	0
Control_2	1	0	1	0	0	0[1]	0[1]	0

[1] The bits labeled as - have to be rewritten with the previous values.

Table 56. Example to clear only MSF (bit 7)

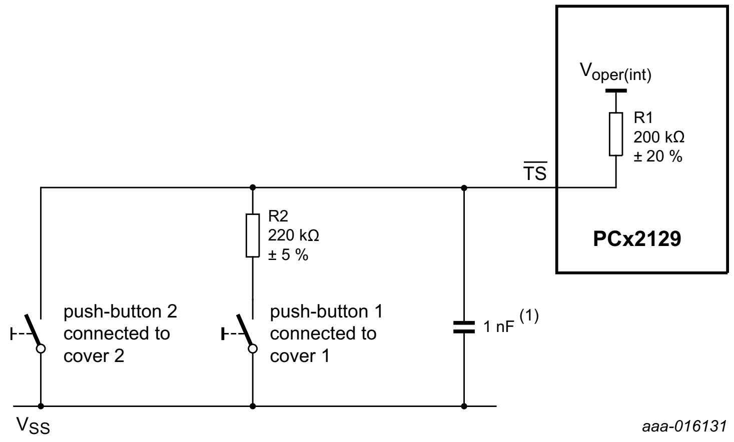
Register	Bit							
	7	6	5	4	3	2	1	0
Control_2	0	0	1	1	0	0[1]	0[1]	0

[1] The bits labeled as - have to be rewritten with the previous values.

8.11 Timestamp function

The PCF2129 has an active LOW timestamp input pin $\overline{\text{TS}}$, internally pulled with an on-chip pull-up resistor to $V_{oper(int)}$. It also has a timestamp detection circuit which can detect two different events:

1. Input on pin $\overline{\text{TS}}$ is driven to an intermediate level between power supply and ground.
2. Input on pin $\overline{\text{TS}}$ is driven to ground.



(1) When using switches or push-buttons, it is recommended to connect a 1 nF capacitance to the $\overline{\text{TS}}$ pin to ensure proper switching.

Fig 20. Timestamp detection with two push-buttons on the $\overline{\text{TS}}$ pin (for example, for tamper detection)

The timestamp function is enabled by default after power-on and it can be switched off by setting the control bit TSOFF (register Timestp_ctl).

A most common application of the timestamp function is described in Ref. 3 “AN11186”.

See Section 8.12.5 for a description of interrupt generation from the timestamp function.

8.11.1 Timestamp flag

1. When the $\overline{\text{TS}}$ input pin is driven to an intermediate level between the power supply and ground, either on the falling edge from V_{DD} or on the rising edge from ground, then the following sequence occurs:
   a. The actual date and time are stored in the timestamp registers.
   b. The timestamp flag TSF1 (register Control_1) is set.
   c. If the TSIE bit (register Control_2) is active, an interrupt on the $\overline{\text{INT}}$ pin is generated.

   The TSF1 flag can be cleared by command. Clearing the flag clears the interrupt. Once TSF1 is cleared, it will only be set again when a new negative or positive edge on pin $\overline{\text{TS}}$ is detected.
2. When the $\overline{\text{TS}}$ input pin is driven to ground, the following sequence occurs:
   a. The actual date and time are stored in the timestamp registers.
   b. In addition to the TSF1 flag, the TSF2 flag (register Control_2) is set.
   c. If the TSIE bit is active, an interrupt on the $\overline{\text{INT}}$ pin is generated.

   The TSF1 and TSF2 flags can be cleared by command; clearing both flags clears the interrupt. Once TSF2 is cleared, it will only be set again when $\overline{\text{TS}}$ pin is driven to ground once again.

8.11.2 Timestamp mode

The timestamp function has two different modes selected by the control bit TSM (timestamp mode) in register Timestp_ctl:

- If TSM is logic 0 (default): in subsequent trigger events without clearing the timestamp flags, the last timestamp event is stored
- If TSM is logic 1: in subsequent trigger events without clearing the timestamp flags, the first timestamp event is stored

The timestamp function also depends on the control bit BTSE in register Control_3, see Section 8.11.4.

8.11.3 Timestamp registers

8.11.3.1 Register Timestp_ctl

Table 57. Timestp_ctl - timestamp control register (address 12h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	TSM	TSOFF	-	1_O_16_TIMESTP[4:0]				
Reset value	0	0	-	X	X	X	X	X

Table 58. Timestp_ctl - timestamp control register (address 12h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**Symbol**	**Value**	**Description**
7	TSM	0	in subsequent events without clearing the timestamp flags, the last event is stored
		1	in subsequent events without clearing the timestamp flags, the first event is stored
6	TSOFF	0	timestamp function active
		1	timestamp function disabled
5	-	-	unused
4 to 0	1_O_16_TIMESTP[4:0]		$^1\!/_{16}$ second timestamp information coded in BCD format

8.11.3.2 Register Sec_timestp

Table 59. Sec_timestp - second timestamp register (address 13h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Symbol	-	SECOND_TIMESTP (0 to 59)						
Reset value	-	X	X	X	X	X	X	X

Table 60. Sec_timestp - second timestamp register (address 13h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	**Symbol**	**Value**	**Place value**	**Description**
7	-	-	-	unused
6 to 4	SECOND_TIMESTP	0 to 5	ten's place	second timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

8.11.3.3 Register Min_timestp

Table 61. Min_timestp - minute timestamp register (address 14h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	MINUTE_TIMESTP (0 to 59)						
Reset value	-	X	X	X	X	X	X	X

Table 62. Min_timestp - minute timestamp register (address 14h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	-	-	-	unused
6 to 4	MINUTE_TIMESTP	0 to 5	ten’s place	minute timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

8.11.3.4 Register Hour_timestp

Table 63. Hour_timestp - hour timestamp register (address 15h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	AMPM	HOUR_TIMESTP (1 to 12) in 12-hour mode				
			HOUR_TIMESTP (0 to 23) in 24-hour mode					
Reset value	-	-	X	X	X	X	X	X

Table 64. Hour_timestp - hour timestamp register (address 15h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 6	-	-	-	unused
12-hour mode[1]				
5	AMPM	0	-	indicates AM
		1	-	indicates PM
4	HOUR_TIMESTP	0 to 1	ten’s place	hour timestamp information coded in BCD format when in 12-hour mode
3 to 0		0 to 9	unit place	
24-hour mode[1]				
5 to 4	HOUR_TIMESTP	0 to 2	ten’s place	hour timestamp information coded in BCD format when in 24-hour mode
3 to 0		0 to 9	unit place	

[1] Hour mode is set by the bit 12_24 in register Control_1.

8.11.3.5 Register Day_timestp

Table 65. Day_timestp - day timestamp register (address 16h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	DAY_TIMESTP (1 to 31)					
Reset value	-	-	X	X	X	X	X	X

Table 66. Day_timestp - day timestamp register (address 16h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 6	-	-	-	unused
5 to 4	DAY_TIMESTP	0 to 3	ten’s place	day timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

8.11.3.6 Register Mon_timestp

Table 67. Mon_timestp - month timestamp register (address 17h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	-	MONTH_TIMESTP (1 to 12)				
Reset value	-	-	-	X	X	X	X	X

Table 68. Mon_timestp - month timestamp register (address 17h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 5	-	-	-	unused
4	MONTH_TIMESTP	0 to 1	ten’s place	month timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

8.11.3.7 Register Year_timestp

Table 69. Year_timestp - year timestamp register (address 18h) bit allocation

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	YEAR_TIMESTP (0 to 99)							
Reset value	X	X	X	X	X	X	X	X

Table 70. Year_timestp - year timestamp register (address 18h) bit description

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 4	YEAR_TIMESTP	0 to 9	ten’s place	year timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

8.11.4 Dependency between Battery switch-over and timestamp

The timestamp function depends on the control bit BTSE in register Control_3:

Table 71. Battery switch-over and timestamp

BTSE	BF	Description
0	- [1]	the battery switch-over does not affect the timestamp registers
1		If a battery switch-over event occurs:
	0 [1]	the timestamp registers store the time and date when the switch-over occurs; after this event occurred BF is set logic 1
	1	the timestamp registers are not modified; in this condition subsequent battery switch-over events or falling edges on pin $\overline{\mathrm{TS}}$ are not registered

[1] Default value.

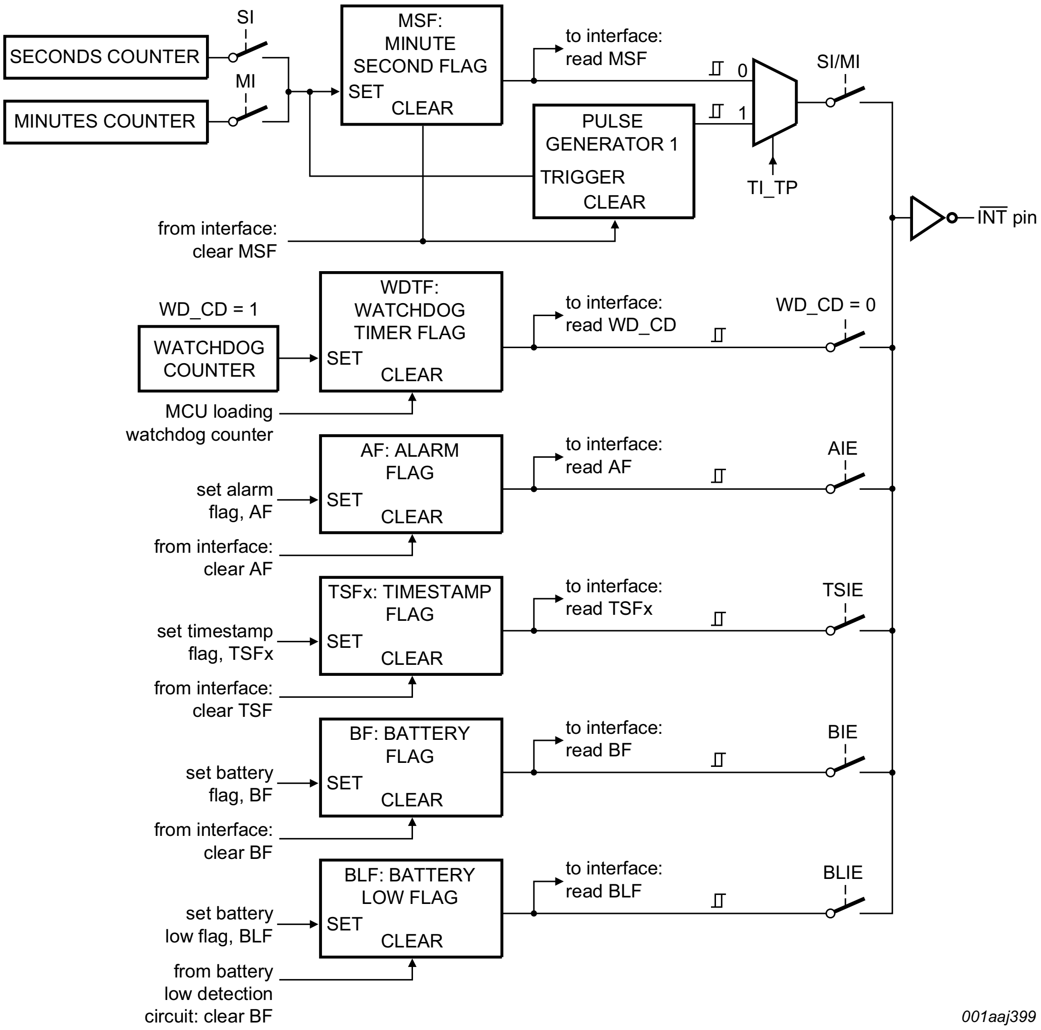
8.12 Interrupt output, $\overline{\mathrm{INT}}$

PCF2129 has an interrupt output pin $\overline{\mathrm{INT}}$ which is open-drain, active LOW (requiring a pull-up resistor if used). Interrupts may be sourced from different places:

- second or minute timer
- watchdog timer
- alarm
- timestamp
- battery switch-over
- battery low detection

The control bit TI_TP (register Watchdg_tim_ctl) is used to configure whether the interrupts generated from the second/minute timer (flag MSF in register Control_2) are pulsed signals or a permanently active signal. All the other interrupt sources generate a permanently active interrupt signal which follows the status of the corresponding flags. When the interrupt sources are all disabled, $\overline{\mathrm{INT}}$ remains high-impedance.

- The flags MSF, AF, TSFx, and BF can be cleared by command.
- The flag WDTF is read only. How it can be cleared is explained in Section 8.10.5.
- The flag BLF is read only. It is cleared automatically from the battery low detection circuit when the battery is replaced.



When SI, MI, WD_CD, AIE, TSIE, BIE, BLIE are all disabled, $\overline{\text{INT}}$ remains high-impedance.

Fig 21. Interrupt block diagram

8.12.1 Minute and second interrupts

Minute and second interrupts are generated by predefined timers. The timers can be enabled independently from one another by the bits MI and SI in register Control_1. However, a minute interrupt enabled on top of a second interrupt cannot be distinguishable since it occurs at the same time.

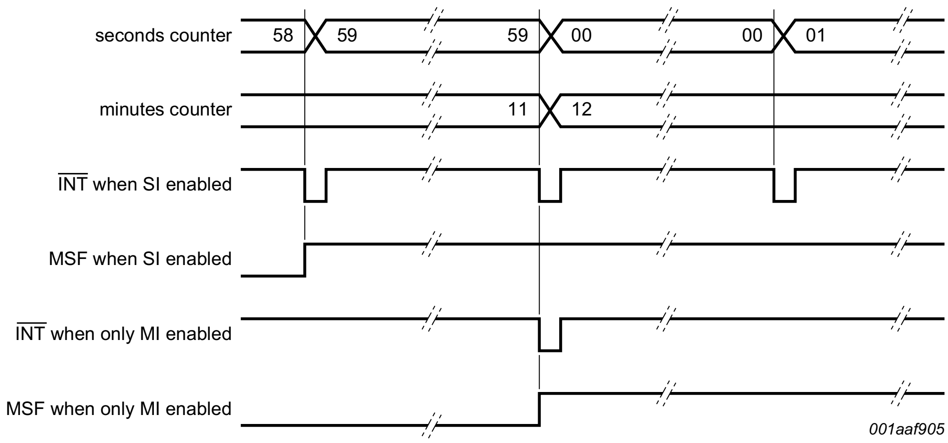
The minute/second flag MSF (register Control_2) is set logic 1 when either the seconds or the minutes counter increments according to the enabled interrupt (see Table 72). The MSF flag can be cleared by command.

Table 72. Effect of bits MI and SI on pin $\overline{\text{INT}}$ and bit MSF

MI	SI	Result on $\overline{\text{INT}}$	Result on MSF
0	0	no interrupt generated	MSF never set
1	0	an interrupt once per minute	MSF set when **minutes** counter increments
0	1	an interrupt once per second	MSF set when **seconds** counter increments
1	1	an interrupt once per second	MSF set when **seconds** counter increments

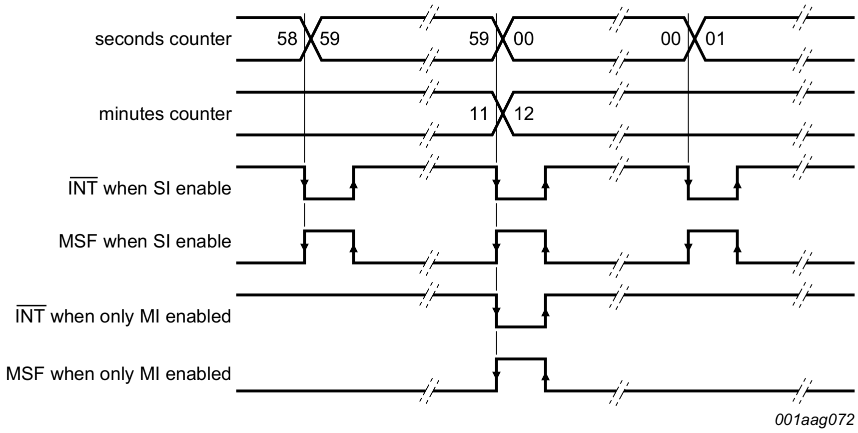
When MSF is set logic 1:

- If TI_TP is logic 1, the interrupt is generated as a pulsed signal.
- If TI_TP is logic 0, the interrupt is permanently active signal that remains until MSF is cleared.



In this example, bit TI_TP is logic 1 and the MSF flag is not cleared after an interrupt.

Fig 22. $\overline{\text{INT}}$ example for SI and MI when TI_TP is logic 1



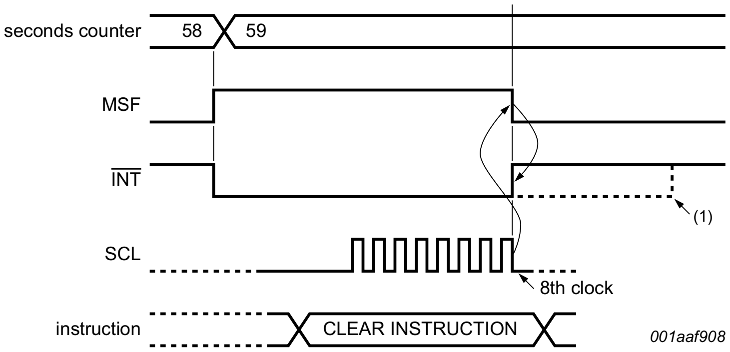
In this example, bit TI_TP is logic 0 and the MSF flag is cleared after an interrupt.

Fig 23. $\overline{\text{INT}}$ example for SI and MI when TI_TP is logic 0

The pulse generator for the minute/second interrupt operates from an internal 64 Hz clock and generates a pulse of $^{1}/_{64}$ seconds in duration.

8.12.2 $\overline{\text{INT}}$ pulse shortening

If the MSF flag (register Control_2) is cleared before the end of the $\overline{\text{INT}}$ pulse, then the $\overline{\text{INT}}$ pulse is shortened. This allows the source of a system interrupt to be cleared immediately when it is serviced, that is, the system does not have to wait for the completion of the pulse before continuing; see Figure 24. Instructions for clearing the bit MSF can be found in Section 8.10.5.



(1) Indicates normal duration of $\overline{\text{INT}}$ pulse.

The timing shown for clearing bit MSF is also valid for the non-pulsed interrupt mode, that is, when TI_TP is logic 0, where the $\overline{\text{INT}}$ pulse may be shortened by setting both bits MI and SI logic 0.

Fig 24. Example of shortening the $\overline{\text{INT}}$ pulse by clearing the MSF flag

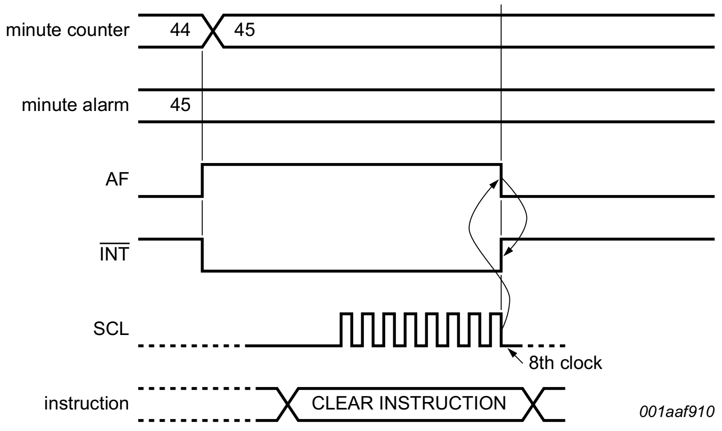
8.12.3 Watchdog timer interrupts

The generation of interrupts from the watchdog timer is controlled using the WD_CD bit (register Watchdg_tim_ctl). The interrupt is generated as an active signal which follows the status of the watchdog timer flag WDTF (register Control_2). No pulse generation is possible for watchdog timer interrupts.

The interrupt is cleared when the flag WDTF is reset. WDTF is a read-only bit and cannot be cleared by command. Instructions for clearing it can be found in Section 8.10.5.

8.12.4 Alarm interrupts

Generation of interrupts from the alarm function is controlled by the bit AIE (register Control_2). If AIE is enabled, the $\overline{\text{INT}}$ pin follows the status of bit AF (register Control_2). Clearing AF immediately clears INT. No pulse generation is possible for alarm interrupts.



Example where only the minute alarm is used and no other interrupts are enabled.

Fig 25. AF timing diagram

8.12.5 Timestamp interrupts

Interrupt generation from the timestamp function is controlled using the TSIE bit (register Control_2). If TSIE is enabled, the $\overline{\text{INT}}$ pin follows the status of the flags TSFx. Clearing the flags TSFx immediately clears $\overline{\text{INT}}$. No pulse generation is possible for timestamp interrupts.

8.12.6 Battery switch-over interrupts

Generation of interrupts from the battery switch-over is controlled by the BIE bit (register Control_3). If BIE is enabled, the $\overline{\text{INT}}$ pin follows the status of bit BF in register Control_3 (see Table 71). Clearing BF immediately clears $\overline{\text{INT}}$. No pulse generation is possible for battery switch-over interrupts.

8.12.7 Battery low detection interrupts

Generation of interrupts from the battery low detection is controlled by the BLIE bit (register Control_3). If BLIE is enabled, the $\overline{\text{INT}}$ pin follows the status of bit BLF (register Control_3). The interrupt is cleared when the battery is replaced (BLF is logic 0) or when bit BLIE is disabled (BLIE is logic 0). BLF is read only and therefore cannot be cleared by command.

8.13 External clock test mode

A test mode is available which allows on-board testing. In this mode, it is possible to set up test conditions and control the operation of the RTC.

The test mode is entered by setting bit EXT_TEST logic 1 (register Control_1). Then pin CLKOUT becomes an input. The test mode replaces the internal clock signal (64 Hz) with the signal applied to pin CLKOUT. Every 64 positive edges applied to pin CLKOUT generate an increment of one second.

The signal applied to pin CLKOUT should have a minimum pulse width of 300 ns and a maximum period of 1000 ns. The internal clock, now sourced from CLKOUT, is divided down by a 2^6 divider chain called prescaler (see Table 73). The prescaler can be set into a known state by using bit STOP. When bit STOP is logic 1, the prescaler is reset to 0. STOP must be cleared before the prescaler can operate again.

From a stop condition, the first 1 second increment will take place after 32 positive edges on pin CLKOUT. Thereafter, every 64 positive edges cause a 1 second increment.

Remark: Entry into test mode is not synchronized to the internal 64 Hz clock. When entering the test mode, no assumption as to the state of the prescaler can be made.

Operating example:

1. Set EXT_TEST test mode (register Control_1, EXT_TEST is logic 1).
2. Set bit STOP (register Control_1, STOP is logic 1).
3. Set time registers to desired value.
4. Clear STOP (register Control_1, STOP is logic 0).
5. Apply 32 clock pulses to CLKOUT.
6. Read time registers to see the first change.
7. Apply 64 clock pulses to CLKOUT.
8. Read time registers to see the second change.

Repeat 7 and 8 for additional increments.

8.14 STOP bit function

The function of the STOP bit is to allow for accurate starting of the time circuits. STOP causes the upper part of the prescaler (F_9 to F_{14}) to be held in reset and thus no 1 Hz ticks are generated. The time circuits can then be set and will not increment until the STOP bit is released. STOP doesn't affect the CLKOUT signal but the output of the prescaler in the range of 32 Hz to 1 Hz (see Figure 26).

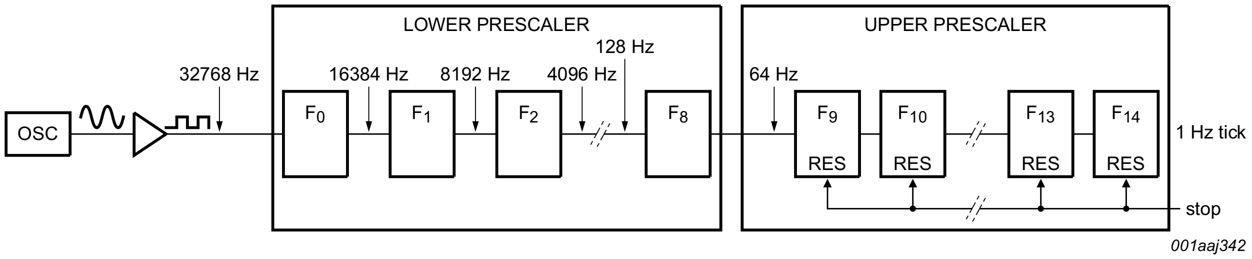
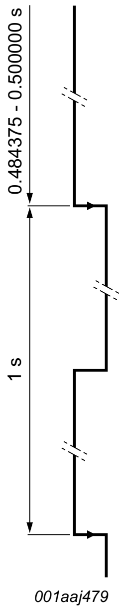


Fig 26. STOP bit functional diagram

The lower stages of the prescaler, F_0 to F_8, are not reset and because the I^2C-bus and the SPI-bus are asynchronous to the crystal oscillator, the accuracy of restarting the time circuits is between 0 and one 64 Hz cycle (0.484375 s and 0.500000 s), see Table 73 and Figure 27.

Table 73. First increment of time circuits after stop release

Bit STOP	Prescaler bits[1] F_0 to F_8 - F_9 to F_{14}	1 Hz tick	Time hh:mm:ss	Comment
Clock is running normally				
0	010000111-010100		12:45:12	prescaler counting normally
STOP bit is activated by user. F_0 to F_8 are not reset and values cannot be predicted externally				
1	xxxxxxxxx-000000		12:45:12	prescaler is reset; time circuits are frozen
New time is set by user				
1	xxxxxxxxx-000000		08:00:00	prescaler is reset; time circuits are frozen
STOP bit is released by user				
0	xxxxxxxxx-000000		08:00:00	prescaler is now running
0	xxxxxxxxx-100000		08:00:00	
0	xxxxxxxxx-100000		08:00:00	
0	xxxxxxxxx-110000		08:00:00	
:	:		:	
0	111111111-111110		08:00:00	
0	000000000-000001		08:00:01	0 to 1 transition of F_{14} increments the time circuits
0	100000000-000001		08:00:01	
:	:		:	
0	111111111-111111		08:00:01	
0	000000000-000000		08:00:01	
0	100000000-000000			
:	:		:	
0	111111111-111110		08:00:01	
0	000000000-000001		08:00:02	0 to 1 transition of F_{14} increments the time circuits

[1] F_0 is clocked at 32.768 kHz.

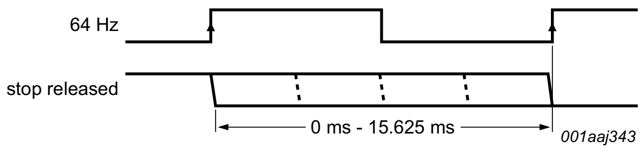


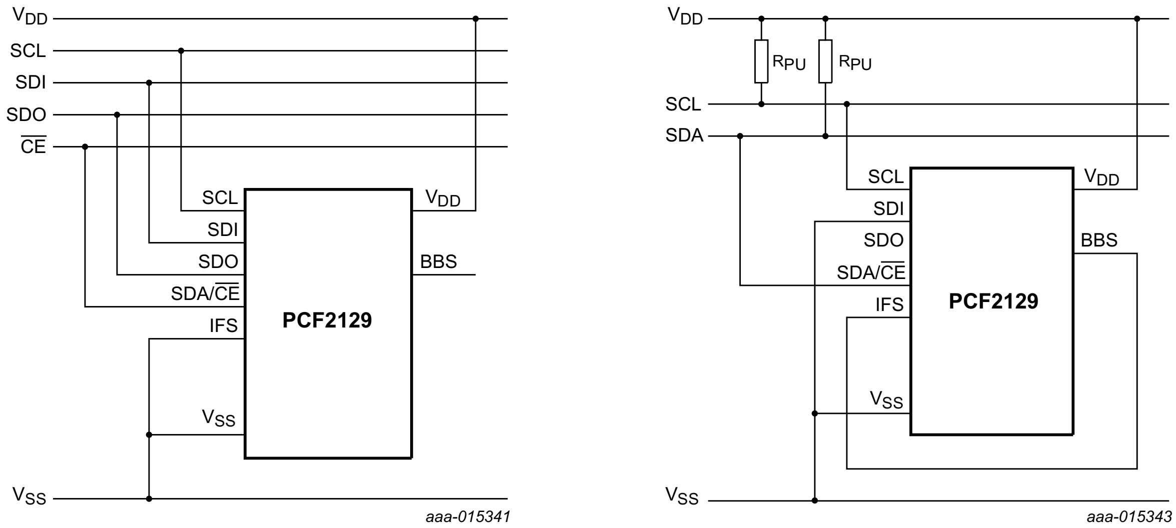
Fig 27. STOP bit release timing

9. Interfaces

The PCF2129 has an I^{2}C-bus or SPI-bus interface using the same pins. The selection is done using the interface selection pin IFS (see Table 74).

Table 74. Interface selection input pin IFS

Pin	Connection	Bus interface	Reference
IFS	V_{SS}	SPI-bus	Section 9.1
	BBS	I^{2}C-bus	Section 9.2



To select the SPI-bus interface, pin IFS has to be connected to pin V_{SS}.

a. SPI-bus interface selection

To select the I^{2}C-bus interface, pin IFS has to be connected to pin BBS.

b. I^{2}C-bus interface selection

Fig 28. Interface selection

9.1 SPI-bus interface

Data transfer to and from the device is made by a 3 line SPI-bus (see Table 75). The data lines for input and output are split. The data input and output line can be connected together to facilitate a bidirectional data bus (see Figure 29). The SPI-bus is initialized whenever the chip enable line pin SDA/$\overline{\text{CE}}$ is inactive.

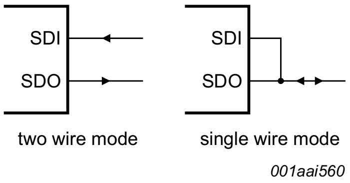


Fig 29. SDI, SDO configurations

Table 75. Serial interface

Symbol	Function	Description
SDA/$\overline{\text{CE}}$	chip enable input; active LOW [1]	when HIGH, the interface is reset; input may be higher than V_{DD}
SCL	serial clock input	when SDA/$\overline{\text{CE}}$ is HIGH, input may float; input may be higher than V_{DD}
SDI	serial data input	when SDA/$\overline{\text{CE}}$ is HIGH, input may float; input may be higher than V_{DD}; input data is sampled on the rising edge of SCL
SDO	serial data output	push-pull output; drives from V_{SS} to $V_{oper(int)}$ (V_{BBS}); output data is changed on the falling edge of SCL

[1] The chip enable must not be wired permanently LOW.

9.1.1 Data transmission

The chip enable signal is used to identify the transmitted data. Each data transfer is a whole byte, with the Most Significant Bit (MSB) sent first.

The transmission is controlled by the active LOW chip enable signal SDA/$\overline{\text{CE}}$. The first byte transmitted is the command byte. Subsequent bytes are either data to be written or data to be read (see Figure 30).

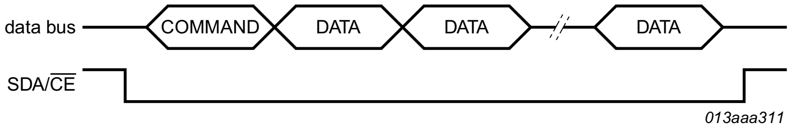
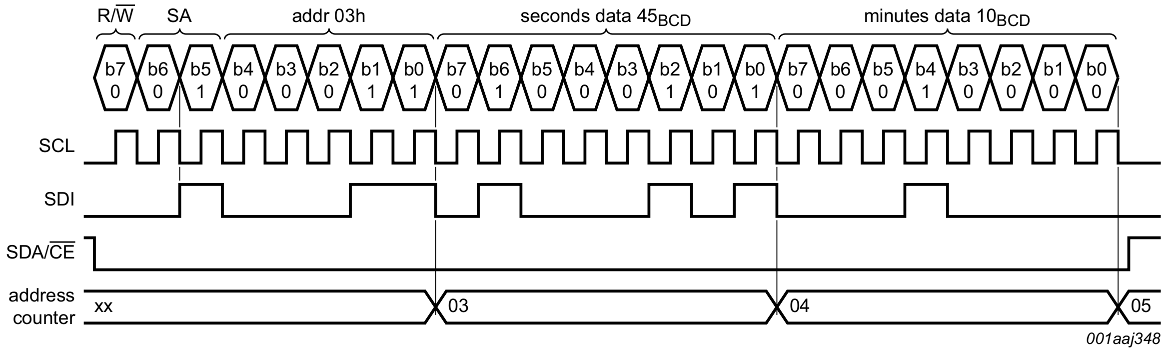


Fig 30. Data transfer overview

The command byte defines the address of the first register to be accessed and the read/write mode. The address counter will auto increment after every access and will reset to zero after the last valid register is accessed. The R/$\overline{\text{W}}$ bit defines if the following bytes are read or write information.

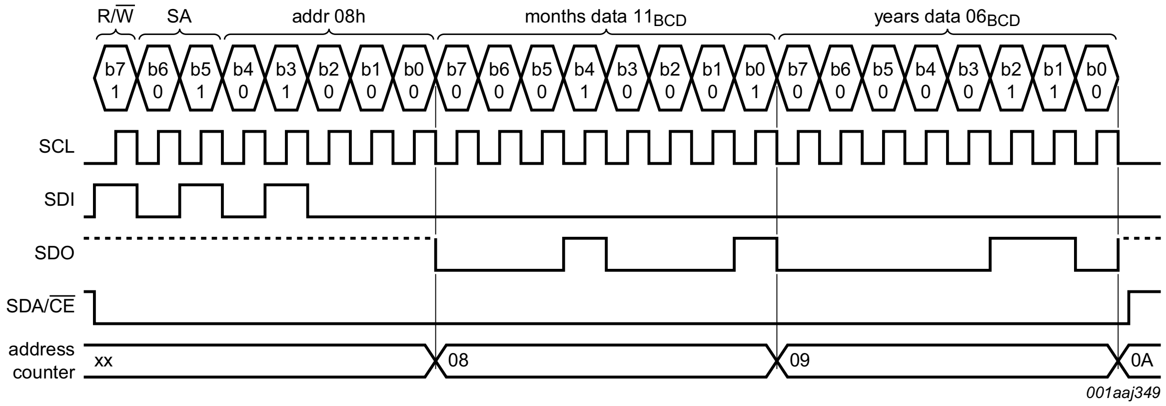
Table 76. Command byte definition

Bit	Symbol	Value	Description
7	R/$\overline{\text{W}}$		data read or write selection
		0	write data
		1	read data
6 to 5	SA	01	subaddress; other codes will cause the device to ignore data transfer
4 to 0	RA	00h to 1Bh	register address



In this example, the Seconds register is set to 45 seconds and the Minutes register to 10 minutes.

Fig 31. SPI-bus write example



In this example, the registers Months and Years are read. The pins SDI and SDO are not connected together. For this configuration, it is important that pin SDI is never left floating. It must always be driven either HIGH or LOW. If pin SDI is left open, high I_{DD} currents may result.

Fig 32. SPI-bus read example

9.2 I^{2}C-bus interface

The I^{2}C-bus is for bidirectional, two-line communication between different ICs or modules. The two lines are a Serial DAta line (SDA) and a Serial CLock line (SCL). Both lines are connected to a positive supply by a pull-up resistor. Data transfer is initiated only when the bus is not busy.

9.2.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line remains stable during the HIGH period of the clock pulse as changes in the data line at this time are interpreted as control signals (see Figure 33).

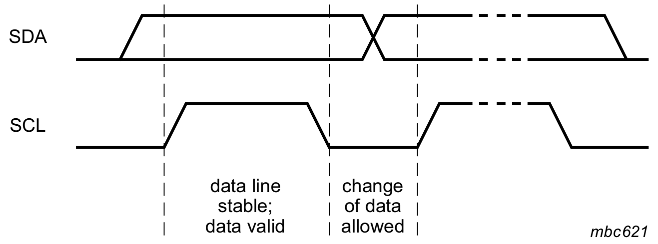


Fig 33. Bit transfer

9.2.2 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH, is defined as the START condition S. A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition P (see Figure 34).

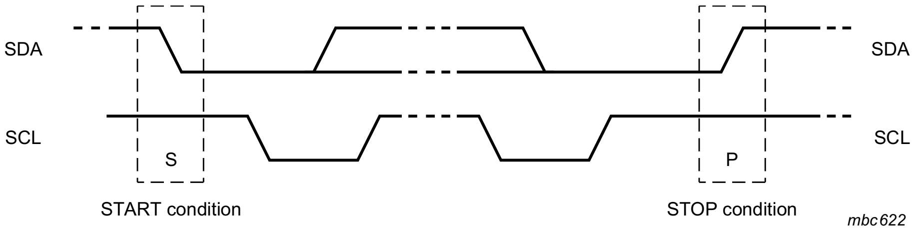


Fig 34. Definition of START and STOP conditions

Remark: For the PCF2129, a repeated START is not allowed. Therefore a STOP has to be released before the next START.

9.2.3 System configuration

A device generating a message is a transmitter; a device receiving a message is the receiver. The device that controls the message is the master; and the devices which are controlled by the master are the slaves.

The PCF2129 can act as a slave transmitter and a slave receiver.

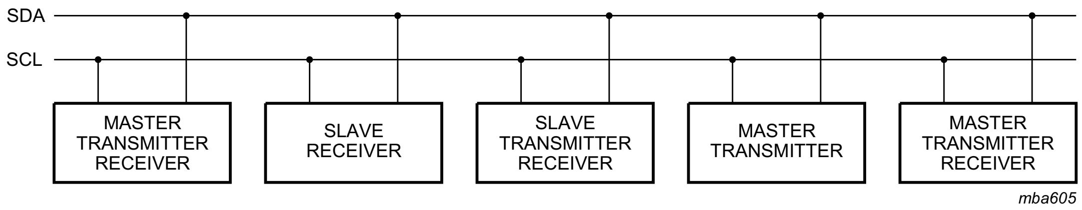


Fig 35. System configuration

9.2.4 Acknowledge

The number of data bytes transferred between the START and STOP conditions from transmitter to receiver is unlimited. Each byte of 8 bits is followed by an acknowledge cycle.

- A slave receiver which is addressed must generate an acknowledge after the reception of each byte.
- Also a master receiver must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter.
- The device that acknowledges must pull-down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse (set-up and hold times must be considered).
- A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.

Acknowledgement on the I^{2}C-bus is illustrated in Figure 36.

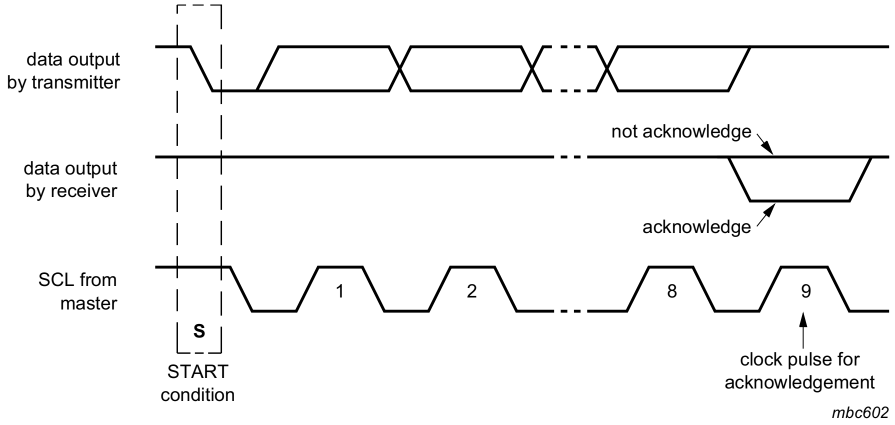


Fig 36. Acknowledgement on the I^{2}C-bus

9.2.5 I^{2}C-bus protocol

After a start condition, a valid hardware address has to be sent to a PCF2129 device. The appropriate I^{2}C-bus slave address is 1010001. The entire I^{2}C-bus slave address byte is shown in Table 77.

Table 77. I²C slave address byte

	Slave address							
Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
	MSB							**LSB**
	1	0	1	0	0	0	1	$R/\overline{W}$

The $R/\overline{W}$ bit defines the direction of the following single or multiple byte data transfer (read is logic 1, write is logic 0).

For the format and the timing of the START condition (S), the STOP condition (P), and the acknowledge (A) refer to the I²C-bus specification Ref. 13 "UM10204" and the characteristics table (Table 82). In the write mode, a data transfer is terminated by sending a STOP condition. A repeated START (Sr) condition is not applicable.

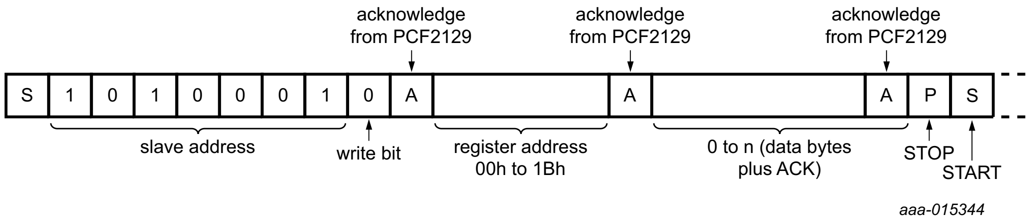


Fig 37. Bus protocol, writing to registers

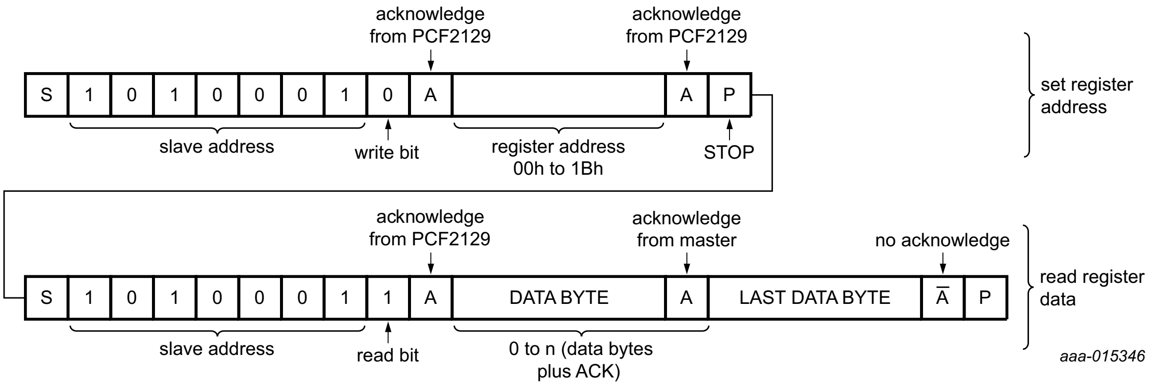


Fig 38. Bus protocol, reading from registers

9.3 Bus communication and battery backup operation

To save power during battery backup operation (see Section 8.5.1), the bus interfaces are inactive. Therefore the communication via I²C- or SPI-bus should be terminated before the supply of the PCF2129 is switched from V_{DD} to V_{BAT}.

Remark: If the I²C-bus communication was terminated uncontrolled, the I²C-bus has to be reinitialized by sending a STOP followed by a START after the device switched back from battery backup operation to V_{DD} supply operation.

10. Internal circuitry

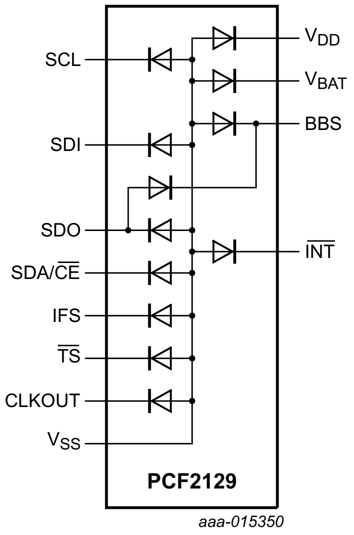


Fig 39. Device diode protection diagram of PCF2129

11. Safety notes

CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

12. Limiting values

Table 78. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		–0.5	+6.5	V
I_{DD}	supply current		–50	+50	mA
V_i	input voltage		–0.5	+6.5	V
I_I	input current		–10	+10	mA
V_O	output voltage		–0.5	+6.5	V
I_O	output current		–10	+10	mA
		at pin SDA/$\overline{\text{CE}}$	–10	+20	mA
V_{BAT}	battery supply voltage		–0.5	+6.5	V
P_{tot}	total power dissipation		-	300	mW
V_{ESD}	electrostatic discharge voltage	HBM [1]	-	±4000	V
		CDM [2]	-	±1250	V
I_{lu}	latch-up current	[3]	-	200	mA
T_{stg}	storage temperature	[4]	–55	+85	°C
T_{amb}	ambient temperature	operating device	–40	+85	°C

[1] Pass level; Human Body Model (HBM) according to Ref. 7 “JESD22-A114”.

[2] Pass level; Charged-Device Model (CDM), according to Ref. 8 “JESD22-C101”.

[3] Pass level; latch-up testing according to Ref. 9 “JESD78” at maximum ambient temperature ($T_{amb(max)}$).

[4] According to the store and transport requirements (see Ref. 14 “UM10569”) the devices have to be stored at a temperature of +8 °C to +45 °C and a humidity of 25 % to 75 %.

13. Static characteristics

Table 79. Static characteristics

V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supplies						
V_{DD}	supply voltage	[1]	1.8	-	4.2	V
V_{BAT}	battery supply voltage		1.8	-	4.2	V
$V_{DD(cal)}$	calibration supply voltage		-	3.3	-	V
V_{low}	low voltage		-	1.2	-	V
I_{DD}	supply current	interface active; supplied by V_{DD}				
		SPI-bus (f_{SCL} = 6.5 MHz)	-	-	800	µA
		I^2C-bus (f_{SCL} = 400 kHz)	-	-	200	µA
		interface inactive (f_{SCL} = 0 Hz)[2]; TCR[1:0] = 00 (see Table 13 on page 12)				
		PWRMNG[2:0] = 111 (see Table 19 on page 16); TSOFF = 1 (see Table 58 on page 41); COF[2:0] = 111 (see Table 15 on page 14)				
		V_{DD} = 1.8 V	-	470	-	nA
		V_{DD} = 3.3 V	-	700	1500	nA
		V_{DD} = 4.2 V	-	800	-	nA
		PWRMNG[2:0] = 111 (see Table 19 on page 16); TSOFF = 1 (see Table 58 on page 41); COF[2:0] = 000 (see Table 15 on page 14)				
		V_{DD} = 1.8 V	-	560	-	nA
		V_{DD} = 3.3 V	-	850	-	nA
		V_{DD} = 4.2 V	-	1050	-	nA
		PWRMNG[2:0] = 000 (see Table 19 on page 16); TSOFF = 0 (see Table 58 on page 41); COF[2:0] = 111 (see Table 15 on page 14)				
		V_{DD} or V_{BAT} = 1.8 V [3]	-	1750	-	nA
		V_{DD} or V_{BAT} = 3.3 V [3]	-	2150	-	nA
		V_{DD} or V_{BAT} = 4.2 V [3]	-	2350	3500	nA
		PWRMNG[2:0] = 000 (see Table 19 on page 16); TSOFF = 0 (see Table 58 on page 41); COF[2:0] = 000 (see Table 15 on page 14)				
		V_{DD} or V_{BAT} = 1.8 V [3]	-	1840	-	nA
		V_{DD} or V_{BAT} = 3.3 V [3]	-	2300	-	nA
		V_{DD} or V_{BAT} = 4.2 V [3]	-	2600	-	nA
$I_{L(bat)}$	battery leakage current	V_{DD} is active supply; V_{BAT} = 3.0 V	-	50	100	nA

Table 79. Static characteristics *…continued*

V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Power management						
$V_{th(sw)bat}$	battery switch threshold voltage		-	2.5	-	V
$V_{th(bat)low}$	low battery threshold voltage		-	2.5	-	V
		T_{amb} = 25 °C	2.25	-	2.85	V
Inputs[4]						
V_I	input voltage		−0.5	-	V_{DD} + 0.5	V
V_{IL}	LOW-level input voltage		-	-	$0.25V_{DD}$	V
		T_{amb} = −20 °C to +85 °C; V_{DD} > 2.0 V	-	-	$0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	-	V
I_{LI}	input leakage current	V_I = V_{DD} or V_{SS}	-	0	-	µA
		post ESD event	−1	-	+1	µA
C_i	input capacitance	[5]	-	-	7	pF
Outputs						
V_O	output voltage	on pins CLKOUT, $\overline{\text{INT}}$, referring to external pull-up	−0.5	-	+5.5	V
		on pin BBS	1.8	-	4.2	V
		on pin SDO	−0.5	-	V_{DD} + 0.5	V
V_{OH}	HIGH output voltage	on pin SDO	$0.8V_{DD}$	-	V_{DD}	V
V_{OL}	LOW output voltage	on pins CLKOUT, $\overline{\text{INT}}$, and SDO	V_{SS}	-	$0.2V_{DD}$	V
I_{OL}	LOW-level output current	output sink current; V_{OL} = 0.4 V				
		on pin SDA/$\overline{\text{CE}}$ [6]	3	17	-	mA
		on all other outputs	1.0	-	-	mA
I_{OH}	HIGH-level output current	output source current; on pin SDO; V_{OH} = 3.8 V; V_{DD} = 4.2 V	1.0	-	-	mA
I_{LO}	output leakage current	V_O = V_{DD} or V_{SS}	-	0	-	µA
		post ESD event	−1	-	+1	µA

[1] For reliable oscillator start-up at power-on: $V_{DD(po)min} = V_{DD(min)} + 0.3$ V.

[2] Timer source clock = $\frac{1}{60}$ Hz, level of pins SDA/$\overline{\text{CE}}$, SDI, and SCL is V_{DD} or V_{SS}.

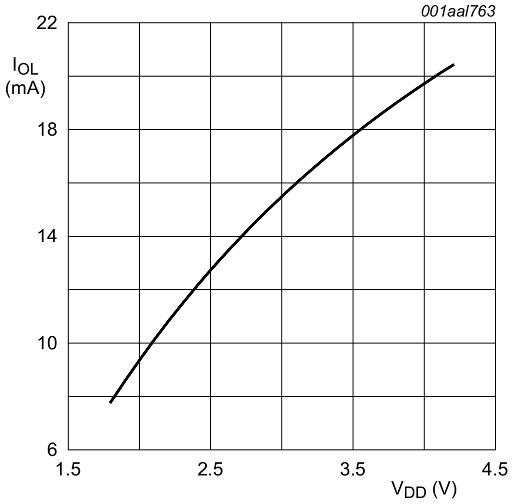
[3] When the device is supplied by the V_{BAT} pin instead of the V_{DD} pin, the current values for I_{BAT} are as specified for I_{DD} under the same conditions.

[4] The I^{2}C-bus and SPI-bus interfaces of PCF2129 are 5 V tolerant.

[5] Tested on sample basis.

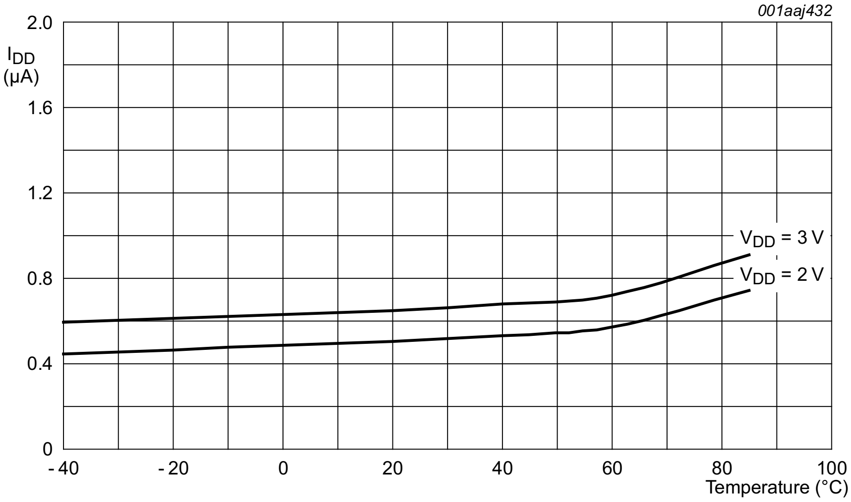
[6] For further information, see Figure 40.

13.1 Current consumption characteristics, typical



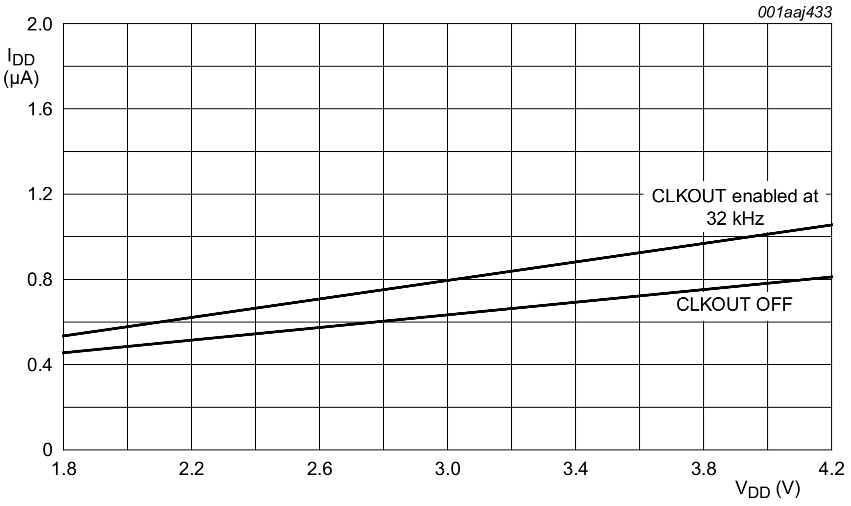
Typical value; V_{OL} = 0.4 V.

Fig 40. **I_{OL} on pin SDA/$\overline{CE}$**

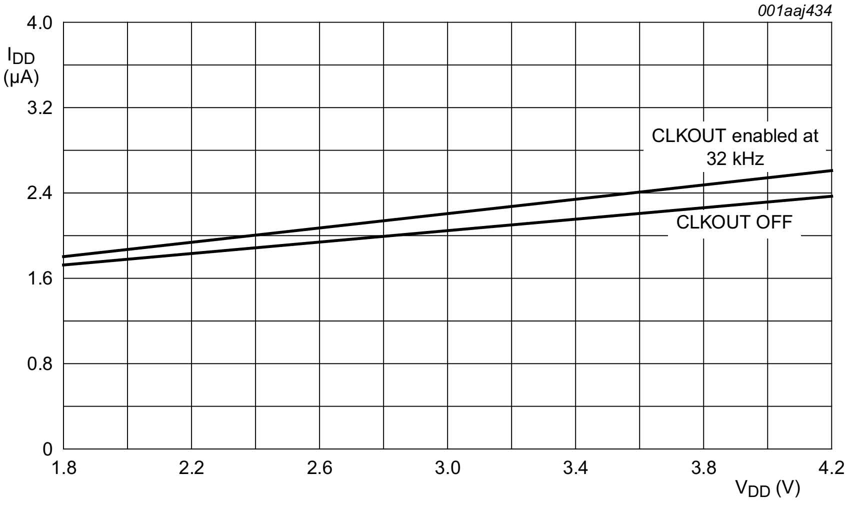


CLKOUT disabled; PWRMNG[2:0] = 111; TSOFF = 1; $\overline{TS}$ input floating.

Fig 41. **I_{DD} as a function of temperature**

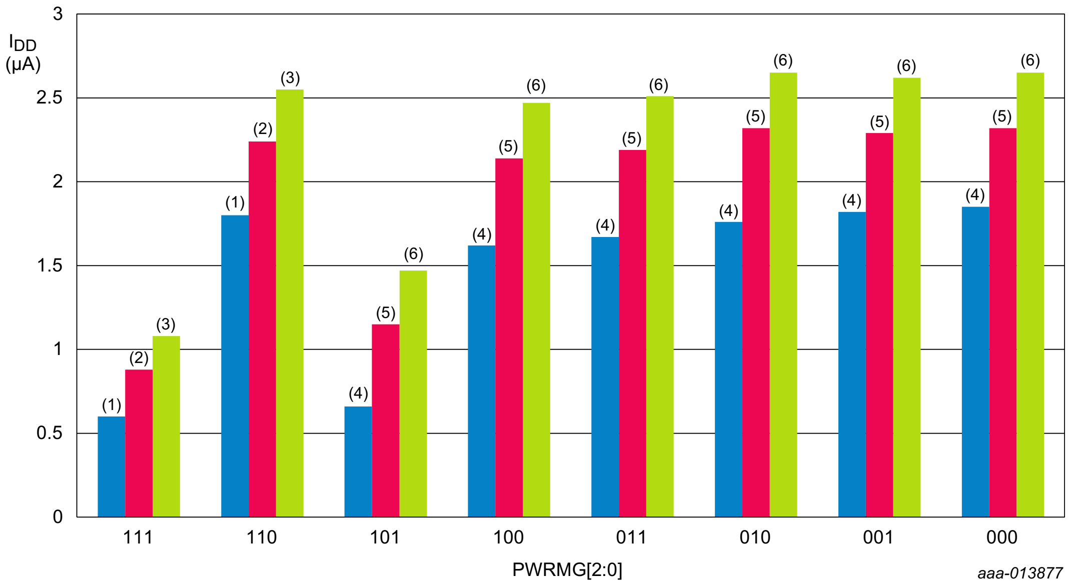


a. PWRMNG[2:0] = 111; TSOFF = 1; T_{amb} = 25 °C; $\overline{TS}$ input floating



b. PWRMNG[2:0] = 000; TSOFF = 0; T_{amb} = 25 °C; $\overline{TS}$ input floating

Fig 42. **I_{DD} as a function of V_{DD}**



Interface inactive; T_{amb} = 25 °C; V_{BAT} = 0 V; default configuration.

Description of the PWRMNG[2:0] settings, see Table 19 on page 16.

(1) V_{DD} = 1.8 V.

(2) V_{DD} = 3.3 V.

(3) V_{DD} = 4.2 V.

(4) V_{DD} or V_{BAT} = 1.8 V.

(5) V_{DD} or V_{BAT} = 3.3 V.

(6) V_{DD} or V_{BAT} = 4.2 V.

Fig 43. Typical I_{DD} as a function of the power management settings

13.2 Frequency characteristics

Table 80. Frequency characteristics

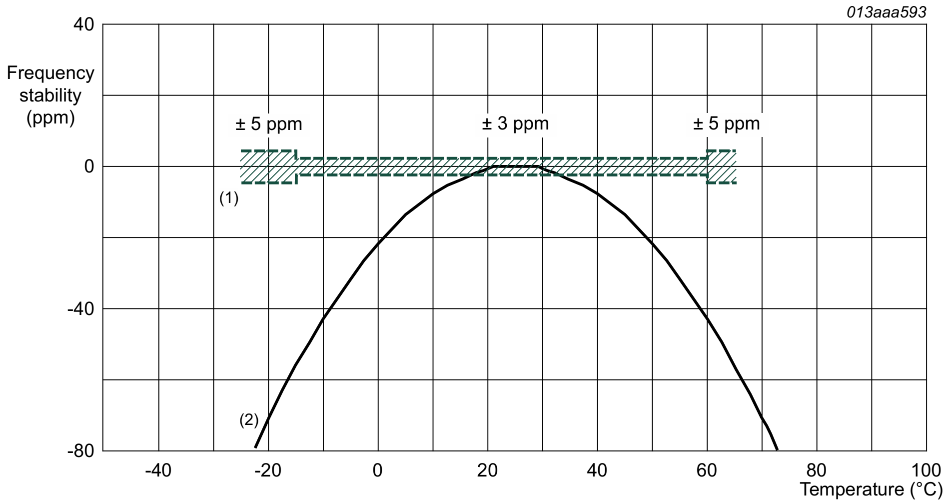
V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = +25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_o	output frequency	on pin CLKOUT; V_{DD} or V_{BAT} = 3.3 V; COF[2:0] = 000; AO[3:0] = 1000	-	32.768	-	kHz
$\Delta f/f$	frequency stability	V_{DD} or V_{BAT} = 3.3 V				
		PCF2129AT				
		T_{amb} = −15 °C to +60 °C [1][2]	-	±3	±5	ppm
		T_{amb} = −25 °C to −15 °C and T_{amb} = +60 °C to +65 °C [1][2]	-	±5	±10	ppm
		PCF2129T				
		T_{amb} = −30 °C to +80 °C [1][2]	-	±3	±8	ppm
		T_{amb} = −40 °C to −30 °C and T_{amb} = +80 °C to +85 °C [1][2]	-	±5	±15	ppm
$\Delta f_{xtal}/f_{xtal}$	relative crystal frequency variation	crystal aging				
		PCF2129AT				
		first year; V_{DD} or V_{BAT} = 3.3 V [3]	-	-	±3	ppm
		PCF2129T				
		first year [3]	-	-	±3	ppm
		ten years	-	-	±8	ppm
$\Delta f/\Delta V$	frequency variation with voltage	on pin CLKOUT	-	±1	-	ppm/V

[1] ±1 ppm corresponds to a time deviation of ±0.0864 seconds per day.

[2] Only valid if CLKOUT frequencies are not equal to 32.768 kHz or if CLKOUT is disabled.

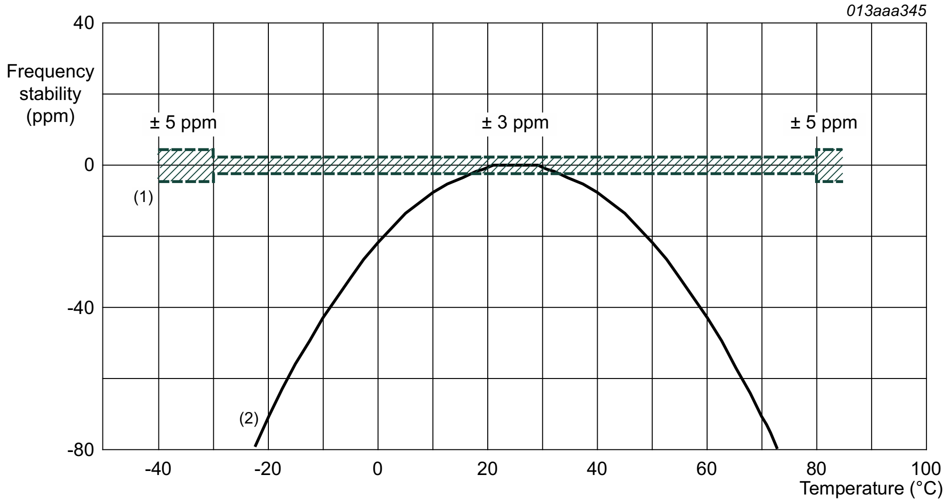
[3] Not production tested. Effects of reflow soldering are included (see Ref. 3 “AN11186”).



(1) Typical temperature compensated frequency response.

(2) Uncompensated typical tuning-fork crystal frequency.

Fig 44. Typical characteristic of frequency with respect to temperature of PCF2129AT



(1) Typical temperature compensated frequency response.

(2) Uncompensated typical tuning-fork crystal frequency.

Fig 45. Typical characteristic of frequency with respect to temperature of PCF2129T

14. Dynamic characteristics

14.1 SPI-bus timing characteristics

Table 81. SPI-bus characteristics

V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C, unless otherwise specified. All timing values are valid within the operating supply voltage at ambient temperature and referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DD} (see Figure 46).

Symbol	Parameter	Conditions	V_{DD} = 1.8 V		V_{DD} = 4.2 V		Unit
			Min	Max	Min	Max	
Pin SCL							
$f_{clk(SCL)}$	SCL clock frequency		-	2.0	-	6.5	MHz
t_{SCL}	SCL time		800	-	140	-	ns
$t_{clk(H)}$	clock HIGH time		100	-	70	-	ns
$t_{clk(L)}$	clock LOW time		400	-	70	-	ns
t_r	rise time	for SCL signal	-	100	-	100	ns
t_f	fall time	for SCL signal	-	100	-	100	ns
Pin SDA/CE							
$t_{su(CE\_N)}$	CE_N set-up time		60	-	30	-	ns
$t_{h(CE\_N)}$	CE_N hold time		40	-	25	-	ns
$t_{rec(CE\_N)}$	CE_N recovery time		100	-	30	-	ns
$t_{w(CE\_N)}$	CE_N pulse width		-	0.99	-	0.99	s
Pin SDI							
t_{su}	set-up time	set-up time for SDI data	70	-	20	-	ns
t_h	hold time	hold time for SDI data	70	-	20	-	ns
Pin SDO							
$t_{d(R)SDO}$	SDO read delay time	C_L = 50 pF	-	225	-	55	ns
$t_{dis(SDO)}$	SDO disable time	[1]	-	90	-	25	ns
$t_{t(SDI-SDO)}$	transition time from SDI to SDO	to avoid bus conflict	0	-	0	-	ns

[1] No load value; bus is held up by bus capacitance; use RC time constant with application values.

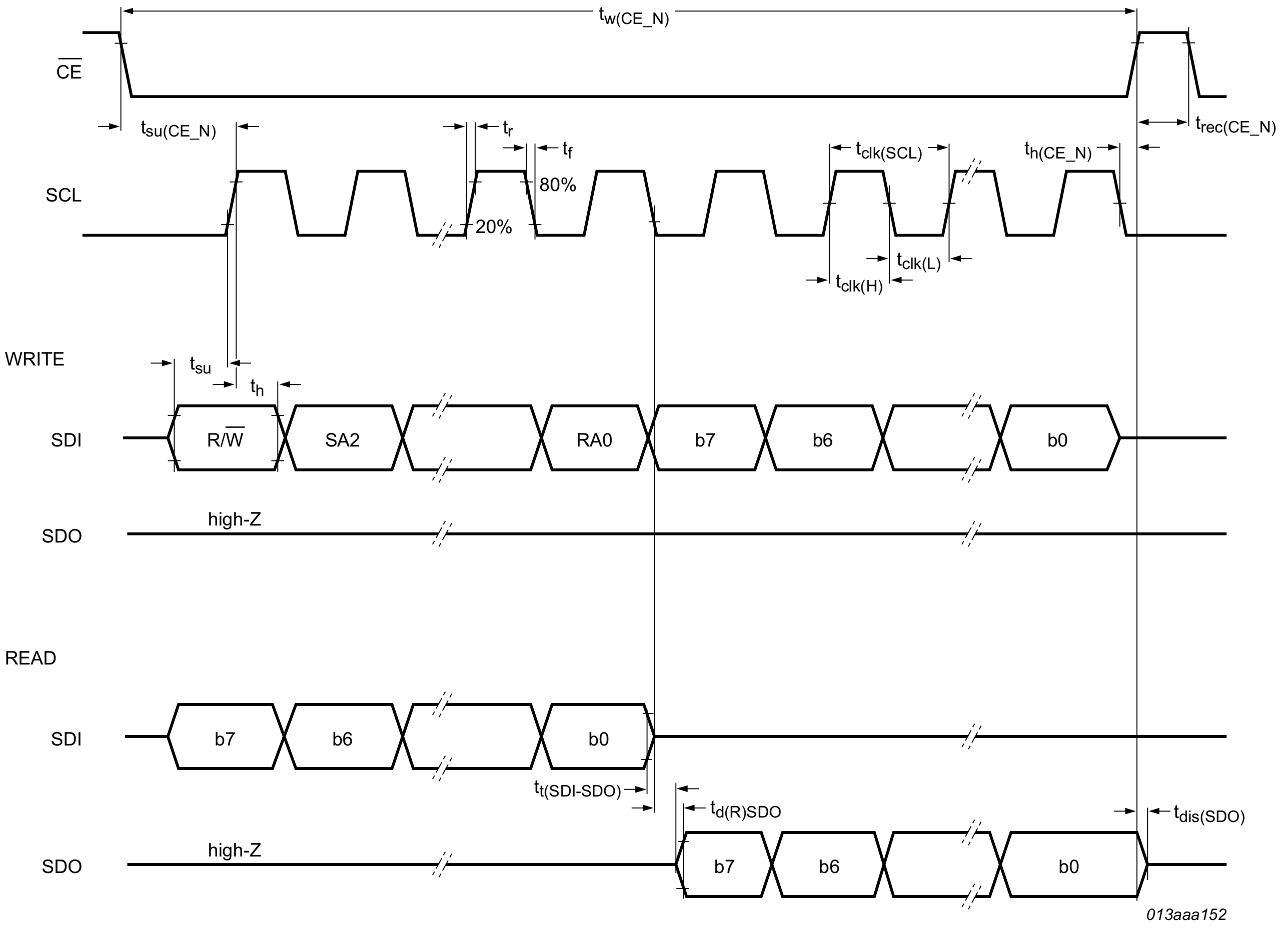


Fig 46. SPI-bus timing

14.2 I²C-bus timing characteristics

Table 82. I²C-bus characteristics

All timing characteristics are valid within the operating supply voltage and ambient temperature range and reference to 30 % and 70 % with an input voltage swing of V_{SS} *to* V_{DD} *(see Figure 47).*

Symbol	Parameter		Standard mode		Fast-mode (Fm)		Unit
			Min	Max	Min	Max	
Pin SCL							
f_{SCL}	SCL clock frequency	[1]	0	100	0	400	kHz
t_{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	µs
t_{HIGH}	HIGH period of the SCL clock		4.0	-	0.6	-	µs
Pin SDA/$\overline{CE}$							
$t_{SU;DAT}$	data set-up time		250	-	100	-	ns
$t_{HD;DAT}$	data hold time		0	-	0	-	ns
Pins SCL and SDA/$\overline{CE}$							
t_{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	-	µs
$t_{SU;STO}$	set-up time for STOP condition		4.0	-	0.6	-	µs
$t_{HD;STA}$	hold time (repeated) START condition		4.0	-	0.6	-	µs
$t_{SU;STA}$	set-up time for a repeated START condition		4.7	-	0.6	-	µs
t_r	rise time of both SDA and SCL signals	[2][3][4]	-	1000	$20 + 0.1C_b$	300	ns
t_f	fall time of both SDA and SCL signals	[2][3][4]	-	300	$20 + 0.1C_b$	300	ns
$t_{VD;ACK}$	data valid acknowledge time	[5]	0.1	3.45	0.1	0.9	µs
$t_{VD;DAT}$	data valid time	[6]	300	-	75	-	ns
t_{SP}	pulse width of spikes that must be suppressed by the input filter	[7]	-	50	-	50	ns

[1] The minimum SCL clock frequency is limited by the bus time-out feature which resets the serial bus interface if either the SDA or SCL is held LOW for a minimum of 25 ms. The bus time-out feature must be disabled for DC operation.

[2] A master device must internally provide a hold time of at least 300 ns for the SDA signal (refer to the V_{IL} of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

[3] C_b is the total capacitance of one bus line in pF.

[4] The maximum t_f for the SDA and SCL bus lines is 300 ns. The maximum fall time for the SDA output stage, t_f is 250 ns. This allows series protection resistors to be connected between the SDA/$\overline{CE}$ pin, the SCL pin, and the SDA/SCL bus lines without exceeding the maximum t_f.

[5] $t_{VD;ACK}$ is the time of the acknowledgement signal from SCL LOW to SDA (out) LOW.

[6] $t_{VD;DAT}$ is the minimum time for valid SDA (out) data following SCL LOW.

[7] Input filters on the SDA and SCL inputs suppress noise spikes of less than 50 ns.

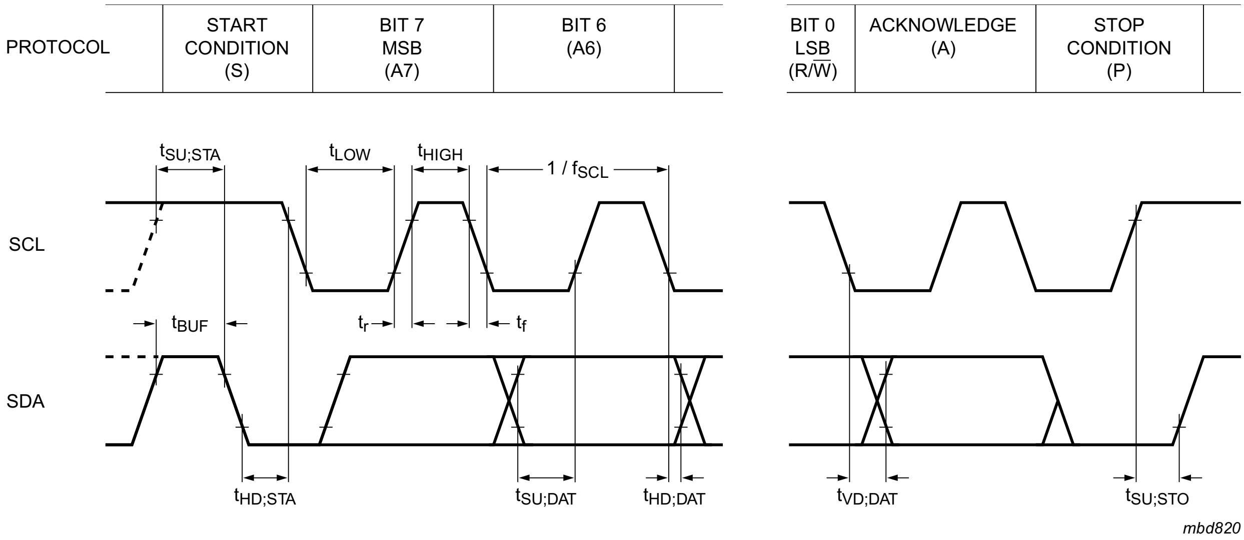
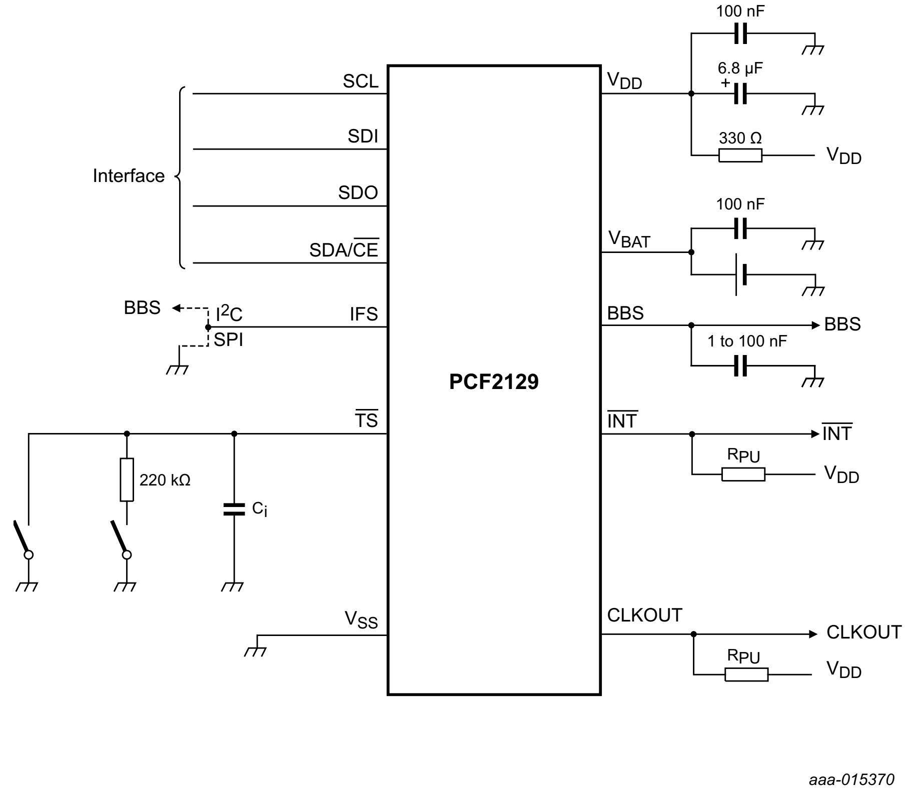


Fig 47. I^{2}C-bus timing diagram; rise and fall times refer to 30 % and 70 %

15. Application information



C_i: In case mechanical switches are used, a capacitor of 1 nF is recommended.

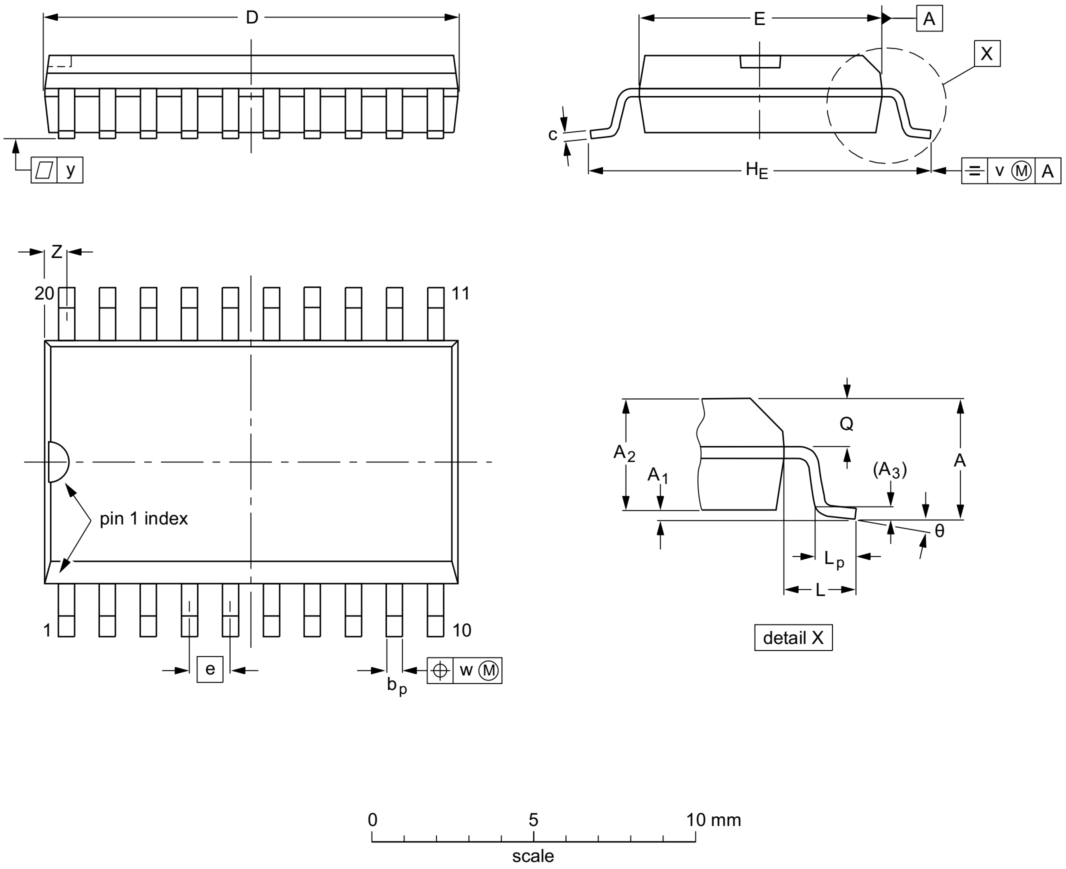
R_{PU}: For example, 10 kΩ.

Fig 48. General application diagram

For information about application configuration, see Ref. 3 “AN11186”.

16. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D(1)	E(1)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

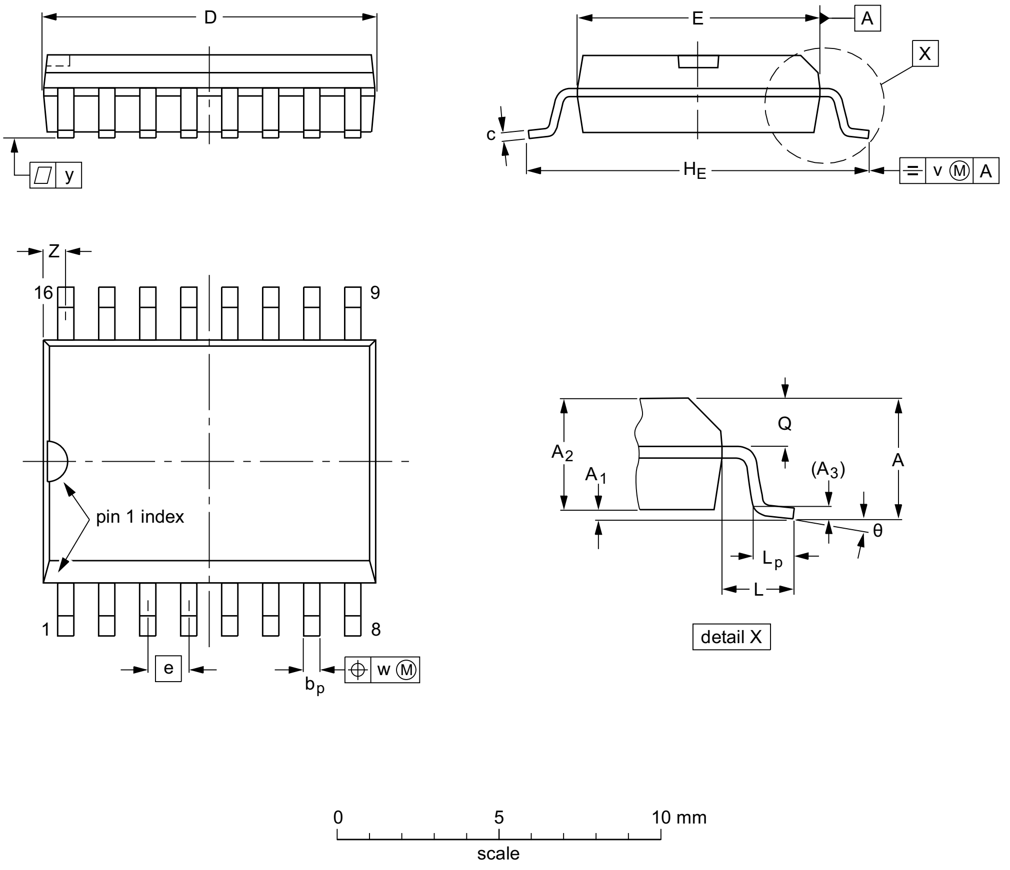
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 49. Package outline SOT163-1 (SO20) of PCF2129AT

SO16: plastic small outline package; 16 leads; body width 7.5 mm **SOT162-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT162-1	075E03	MS-013				~~99-12-27~~ 03-02-19

Fig 50. Package outline SOT162-1 (SO16) of PCF2129T

17. Packing information

17.1 Tape and reel information

For tape and reel packing information, see

- Ref. 11 "SOT162-1_518" on page 78 for the PCF2129T.
- Ref. 12 "SOT163-1_518" on page 78 for the PCF2129AT.

18. Soldering

For information about soldering, see Ref. 3 "AN11186".

18.1 Footprint information

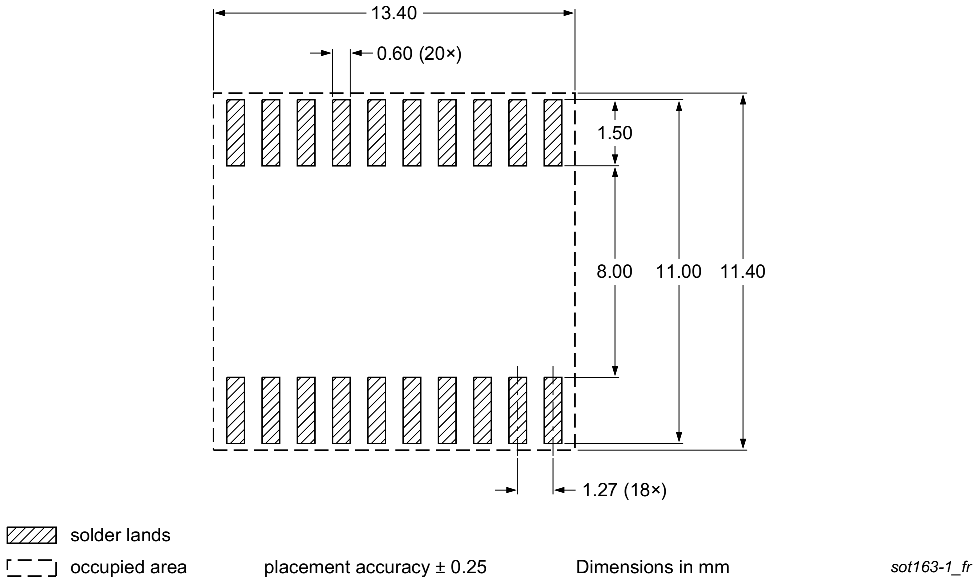
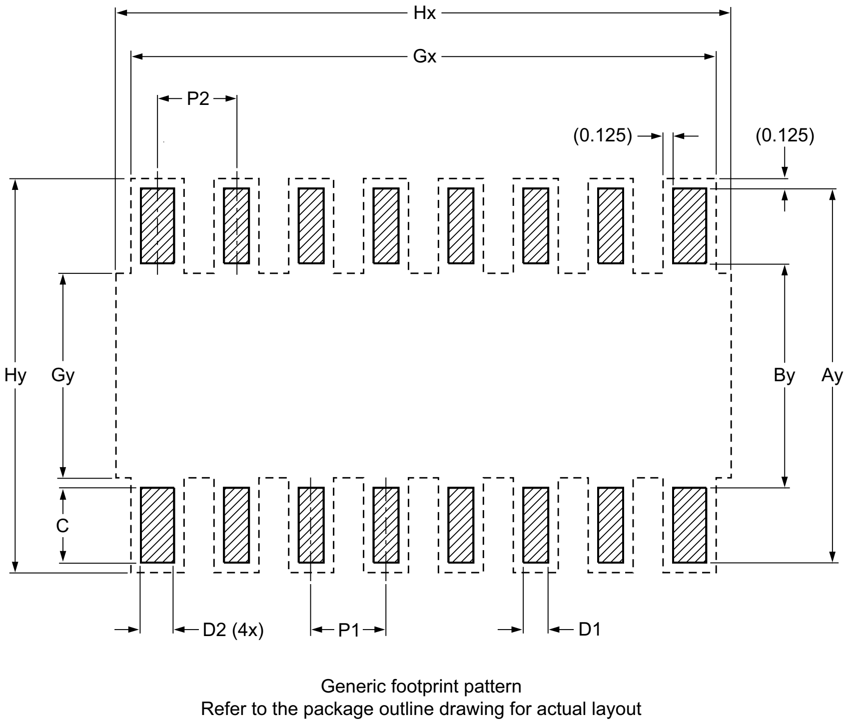


Fig 51. Footprint information for reflow soldering of SOT163-1 (SO20) of PCF2129AT

Footprint information for reflow soldering of SO16 package **SOT162-1**



▨ solder land

- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
1.270	1.320	11.200	6.400	2.400	0.700	0.800	10.040	8.600	11.900	11.450

sot162-1_fr

Fig 52. Footprint information for reflow soldering of SOT162-1 (SO16) of PCF2129T

19. Appendix

19.1 Real-Time Clock selection

Table 83. Selection of Real-Time Clocks

Type name	Alarm, Timer, Watchdog	Interrupt output	Interface	I_{DD}, typical (nA)	Battery backup	Timestamp, tamper input	AEC-Q100 compliant	Special features	Packages
PCF8563	X	1	I^{2}C	250	-	-	-	-	SO8, TSSOP8, HVSON10
PCF8564A	X	1	I^{2}C	250	-	-	-	integrated oscillator caps	WLCSP
PCA8565	X	1	I^{2}C	600	-	-	grade 1	high robustness, T_{amb}= −40 °C to 125 °C	TSSOP8, HVSON10
PCA8565A	X	1	I^{2}C	600	-	-	-	integrated oscillator caps, T_{amb}= −40 °C to 125 °C	WLCSP
PCF85063	-	1	I^{2}C	220	-	-	-	basic functions only, no alarm	HXSON8
PCF85063A	X	1	I^{2}C	220	-	-	-	tiny package	SO8, DFN2626-10
PCF85063B	X	1	SPI	220	-	-	-	tiny package	DFN2626-10
PCF85263A	X	2	I^{2}C	230	X	X	-	time stamp, battery backup, stopwatch $^{1}/_{100}$ s	SO8, TSSOP10, TSSOP8, DFN2626-10
PCF85263B	X	2	SPI	230	X	X	-	time stamp, battery backup, stopwatch $^{1}/_{100}$s	TSSOP10, DFN2626-10
PCF85363A	X	2	I^{2}C	230	X	X	-	time stamp, battery backup, stopwatch $^{1}/_{100}$s, 64 Byte RAM	TSSOP10, DFN2626-10
PCF85363B	X	2	SPI	230	X	X	-	time stamp, battery backup, stopwatch $^{1}/_{100}$s, 64 Byte RAM	TSSOP10, DFN2626-10
PCF8523	X	2	I^{2}C	150	X	-	-	lowest power 150 nA in operation, FM+ 1 MHz	SO8, HVSON8, TSSOP14, WLCSP
PCF2123	X	1	SPI	100	-	-	-	lowest power 100 nA in operation	TSSOP14, HVQFN16
PCF2127	X	1	I^{2}C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated, 512 Byte RAM	SO16

Table 83. Selection of Real-Time Clocks *…continued*

Type name	Alarm, Timer, Watchdog	Interrupt output	Interface	I_{DD}, typical (nA)	Battery backup	Timestamp, tamper input	AEC-Q100 compliant	Special features	Packages
PCF2127A	X	1	I^2C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated, 512 Byte RAM	SO20
PCF2129	X	1	I^2C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated	SO16
PCF2129A	X	1	I^2C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated	SO20
PCA2129	X	1	I^2C and SPI	500	X	X	grade 3	temperature compensated, quartz built in, calibrated	SO16
PCA21125	X	1	SPI	820	-	-	grade 1	high robustness, T_{amb}= –40 °C to 125 °C	TSSOP14

20. Abbreviations

Table 84. Abbreviations

Acronym	Description
AM	Ante Meridiem
BCD	Binary Coded Decimal
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DC	Direct Current
GPS	Global Positioning System
HBM	Human Body Model
I^{2}C	Inter-Integrated Circuit
IC	Integrated Circuit
LSB	Least Significant Bit
MCU	Microcontroller Unit
MM	Machine Model
MSB	Most Significant Bit
PM	Post Meridiem
POR	Power-On Reset
PORO	Power-On Reset Override
PPM	Parts Per Million
RC	Resistance-Capacitance
RTC	Real-Time Clock
SCL	Serial CLock line
SDA	Serial DAta line
SPI	Serial Peripheral Interface
SRAM	Static Random Access Memory
TCXO	Temperature Compensated Xtal Oscillator
Xtal	crystal

21. References

[1] **AN10365 —** Surface mount reflow soldering description

[2] **AN10853 —** Handling precautions of ESD sensitive devices

[3] **AN11186 —** Application and soldering information for the PCA2129 and PCF2129 TCXO RTC

[4] **IEC 60134 —** Rating systems for electronic tubes and valves and analogous semiconductor devices

[5] **IEC 61340-5 —** Protection of electronic devices from electrostatic phenomena

[6] **IPC/JEDEC J-STD-020D —** Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices

[7] **JESD22-A114 —** Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)

[8] **JESD22-C101 —** Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components

[9] **JESD78 —** IC Latch-Up Test

[10] **JESD625-A —** Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices

[11] **SOT162-1_518 —** SO16; Reel pack; SMD, 13”, packing information

[12] **SOT163-1_518 —** SO20; Reel pack; SMD, 13”, packing information

[13] **UM10204 —** I^{2}C-bus specification and user manual

[14] **UM10569 —** Store and transport requirements

[15] **UM10762 —** User manual for the accurate RTC demo board OM13513 containing PCF2127T and PCF2129AT

22. Revision history

Table 85. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCF2129 v.7	20141219	Product data sheet	-	PCF2129AT v.6 PCF2129T v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Combined PCF2129AT and PCF2129T data sheets to one data sheet • Added Figure 4, Figure 43 and Figure 48 • Enhanced Figure 8, Figure 12, Figure 20, Section 8.11.1, Figure 37, Figure 38 • Added Section 9.3 • Changed I_{DD} values in Table 79 • Added V_{OH} and V_{OL} values in Table 79 • Enhanced description of internal operating voltage • Added register bit allocation tables • Enhanced ESD HBM values • Fixed typos			
PCF2129AT				
PCF2127AT v.6	20130711	Product data sheet	-	PCF2127AT v.5
PCF2129AT v.5	20130212	Product data sheet	-	PCF2129AT v.4
PCF2129AT v.4	20121107	Product data sheet	-	PCF2129AT v.3
PCF2129AT v.3	20121004	Product data sheet	-	PCF2129AT v.2
PCF2129AT v.2	20100507	Product data sheet	-	PCF2129AT v.1
PCF2129AT v.1	20100113	Product data sheet	-	-
PCF2129T				
PCF2129T v.4	20130711	Product data sheet	-	PCF2129T v.3
PCF2129T v.3	20130212	Product data sheet	-	PCF2129T v.2
PCF2129T v.2	20121025	Product data sheet	-	PCF2129T v.1
PCF2129T v.1	20120618	Product data sheet	-	-

23. Legal information

23.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term ‘short data sheet’ is explained in section “Definitions”.

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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25. Tables

26. Figures

27. Contents

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Date of release: 19 December 2014
Document identifier: PCF2129

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